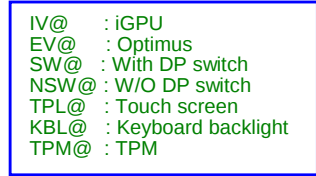
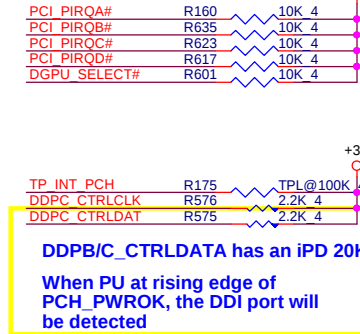


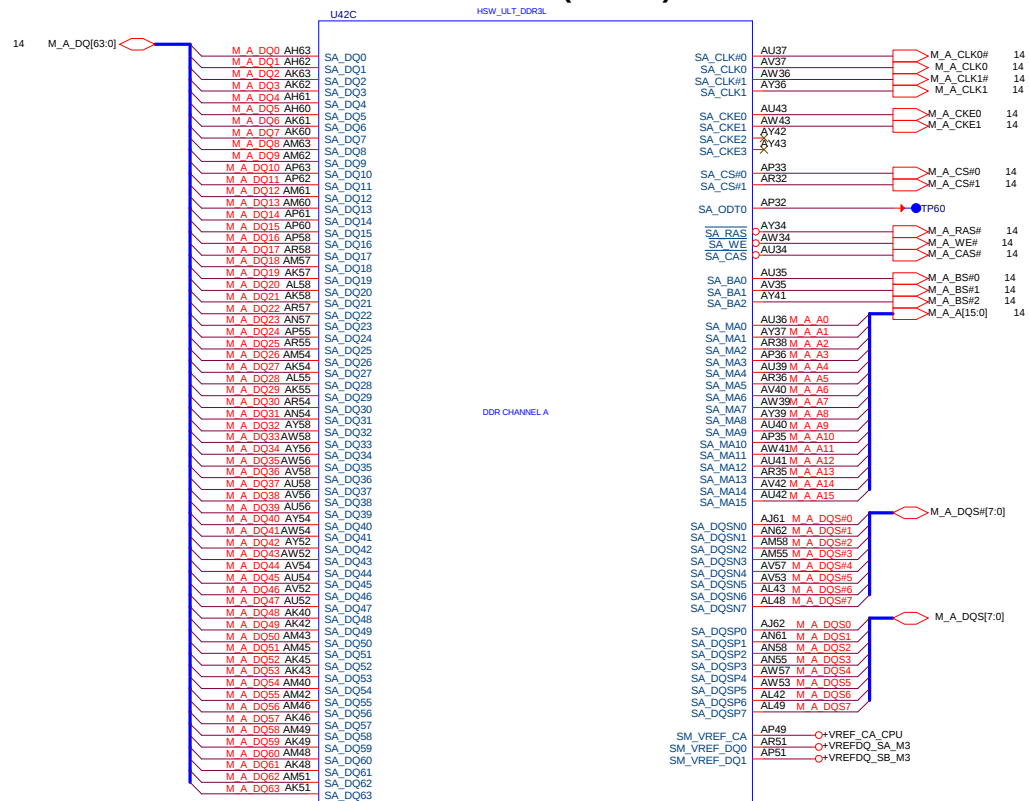
01



02

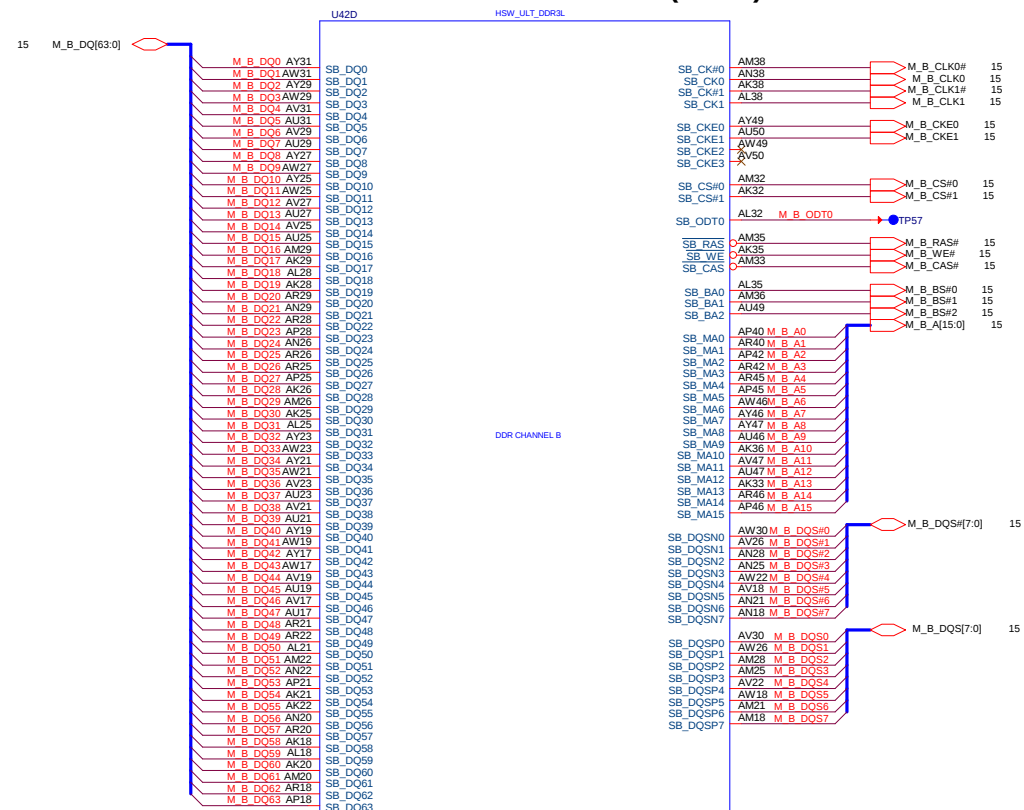


Haswell ULT (DDR3L)



3 OF 19

Haswell Processor (DDR3)



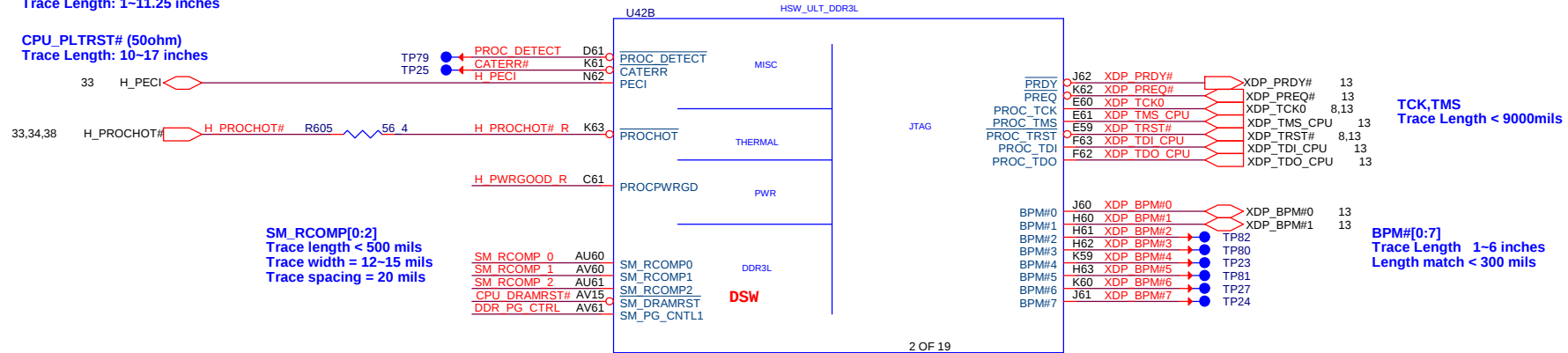
4 OF 19

Haswell ULT (SIDE BAND)

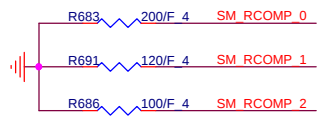
H_PECI (50ohm)
Route on microstrip only
Spacing >18 mils
Trace Length: 0.4~6.125 inches

H_PWRGOOD (50ohm)
Trace Length: 1~11.25 inches

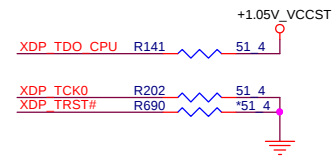
CPU_PLTRST# (50ohm)
Trace Length: 10~17 inches



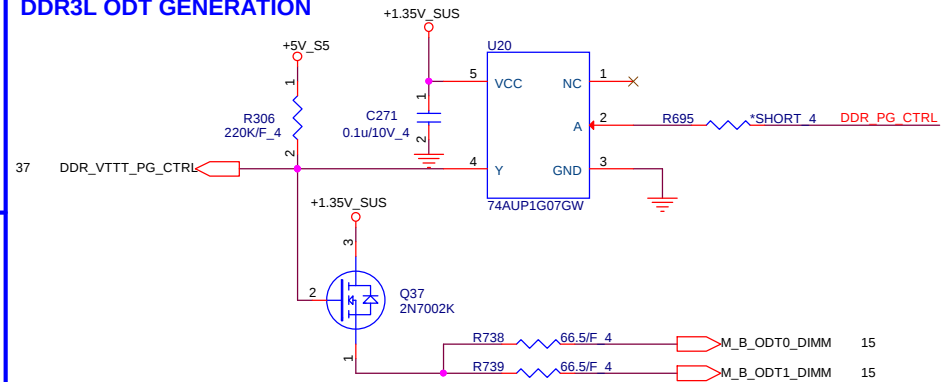
DRAM COMP



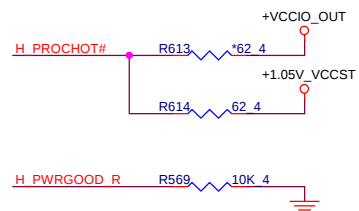
XDP PU/PD



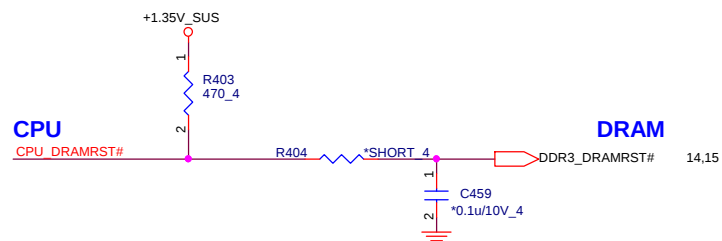
DDR3L ODT GENERATION



PU/PD of CPU



DRAMRST



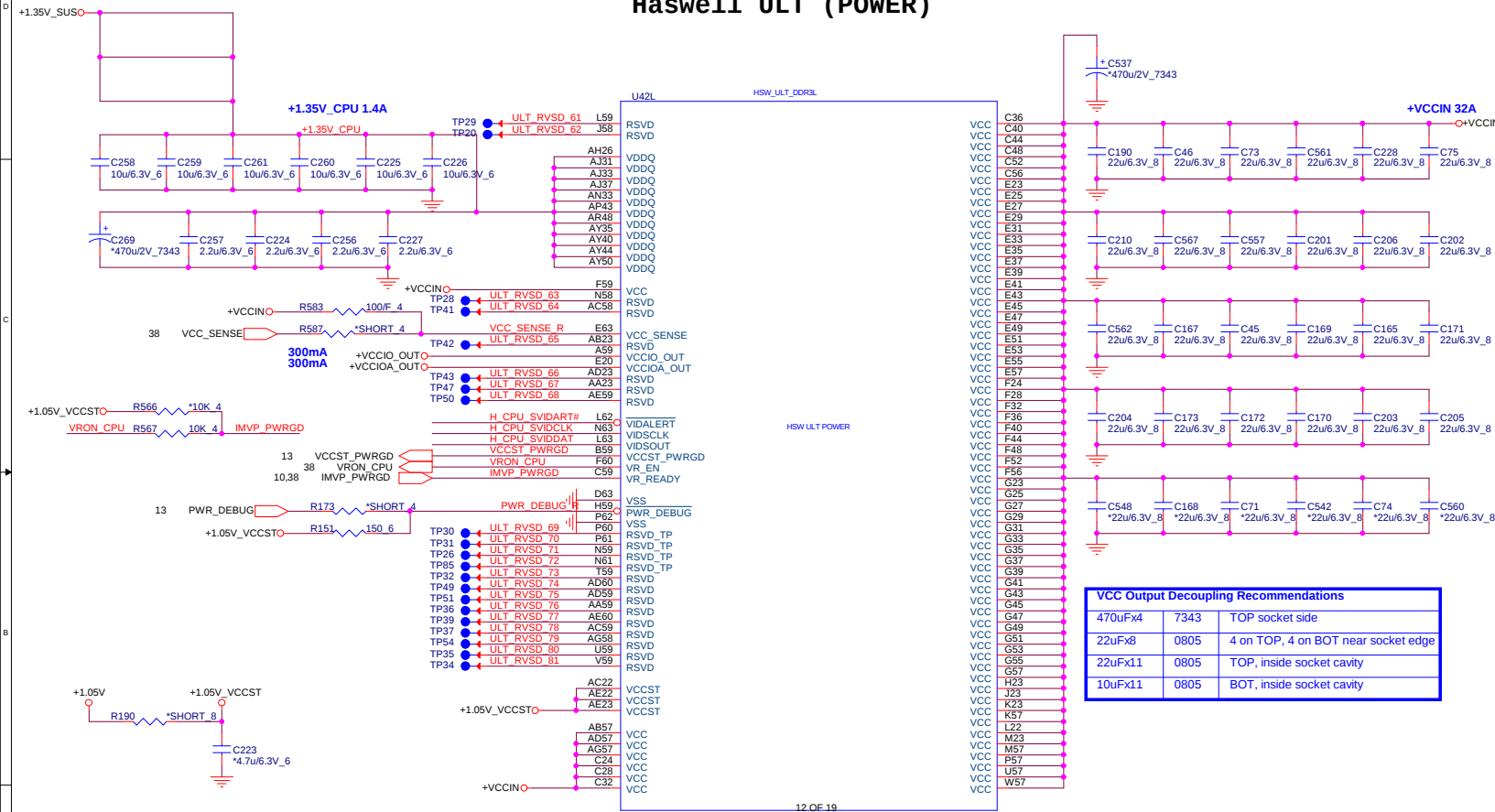
Quanta Computer Inc.

PROJECT : ZRQ

Size	Document Number	Rev
	Haswell 1/5 (PEG/DMI/FDI)	3A
Date:	Friday, April 12, 2013	Sheet 4 of 47

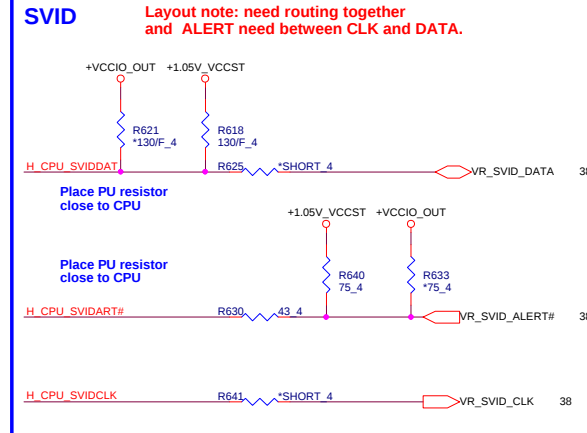
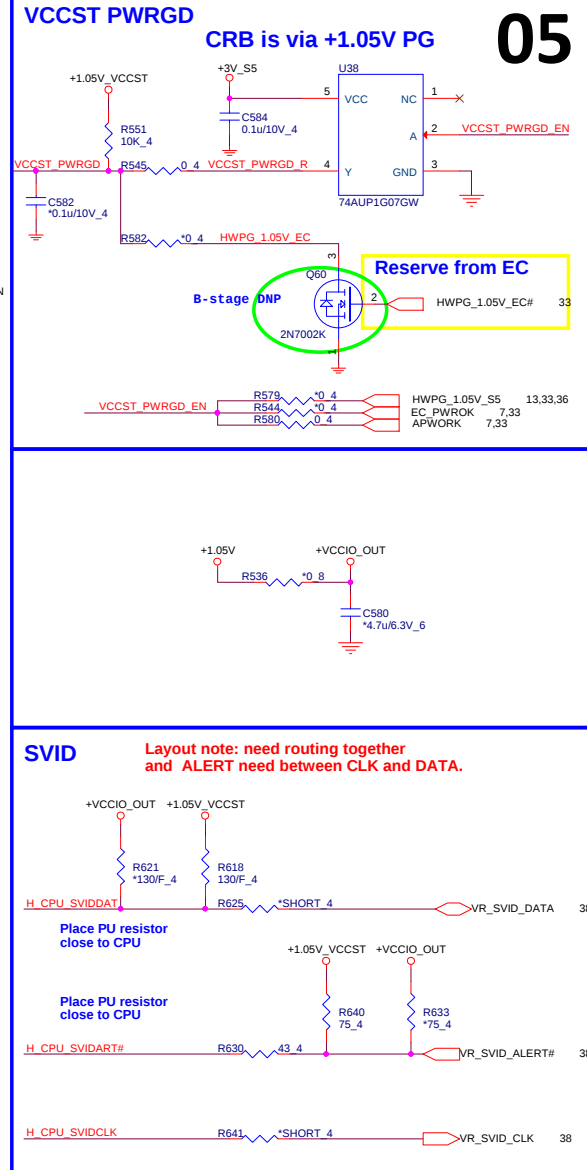
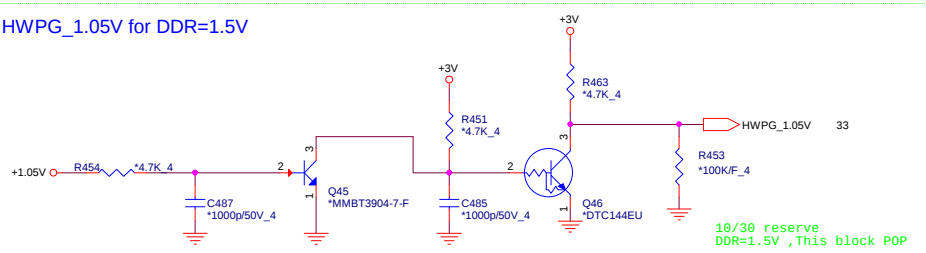
VDDQ Output Decoupling Recommendations			
330uFx2	7343	BOT socket side	
22uFx11	0805	5 on TOP, 6 on BOT inside socket cavity	
10uFx10	0805	5 on TOP, 5 on BOT inside socket cavity	

Haswell ULT (POWER)



VCC Output Decoupling Recommendations			
470uFx4	7343	TOP socket side	
22uFx8	0805	4 on TOP, 4 on BOT near socket edge	
22uFx11	0805	TOP, inside socket cavity	
10uFx11	0805	BOT, inside socket cavity	

HWPG_1.05V for DDR=1.5V





5.33

APWORK R413 0.4 APWROK R

Speed up 250ms to boot up
for EC power on 250 ms

 R414
10K_4

PCH ACPIPRESENT
 PCH BATLOW#
 PCIE LAN WAKE#
 PCH PWRBTN#

R259 *10K 4
 R262 *8.2K 4
 R264 *10K 4
 R261 *10K 4

+3V_S5

+3VPCU

R272 10K 4
 R275 8.2K 4
 R276 1K 4
 R273 *10K 4

Non Deep Sx

The schematic diagram illustrates the Non Deep Sx circuit. It features a 3V_S5 supply connected to a network of components. A capacitor C282 (0.33u/10V_6) is connected to the supply. A resistor R302 (100K_4) is connected to the supply. A resistor R300 (0.6) is connected to the supply. A MOSFET Q34 (AO3413) is connected to the supply. A resistor R303 (SHORT_6) is connected to the supply. A MOSFET Q35 (2N7002K) is connected to the supply. The circuit is controlled by a signal PCH_SLP_SUS#.

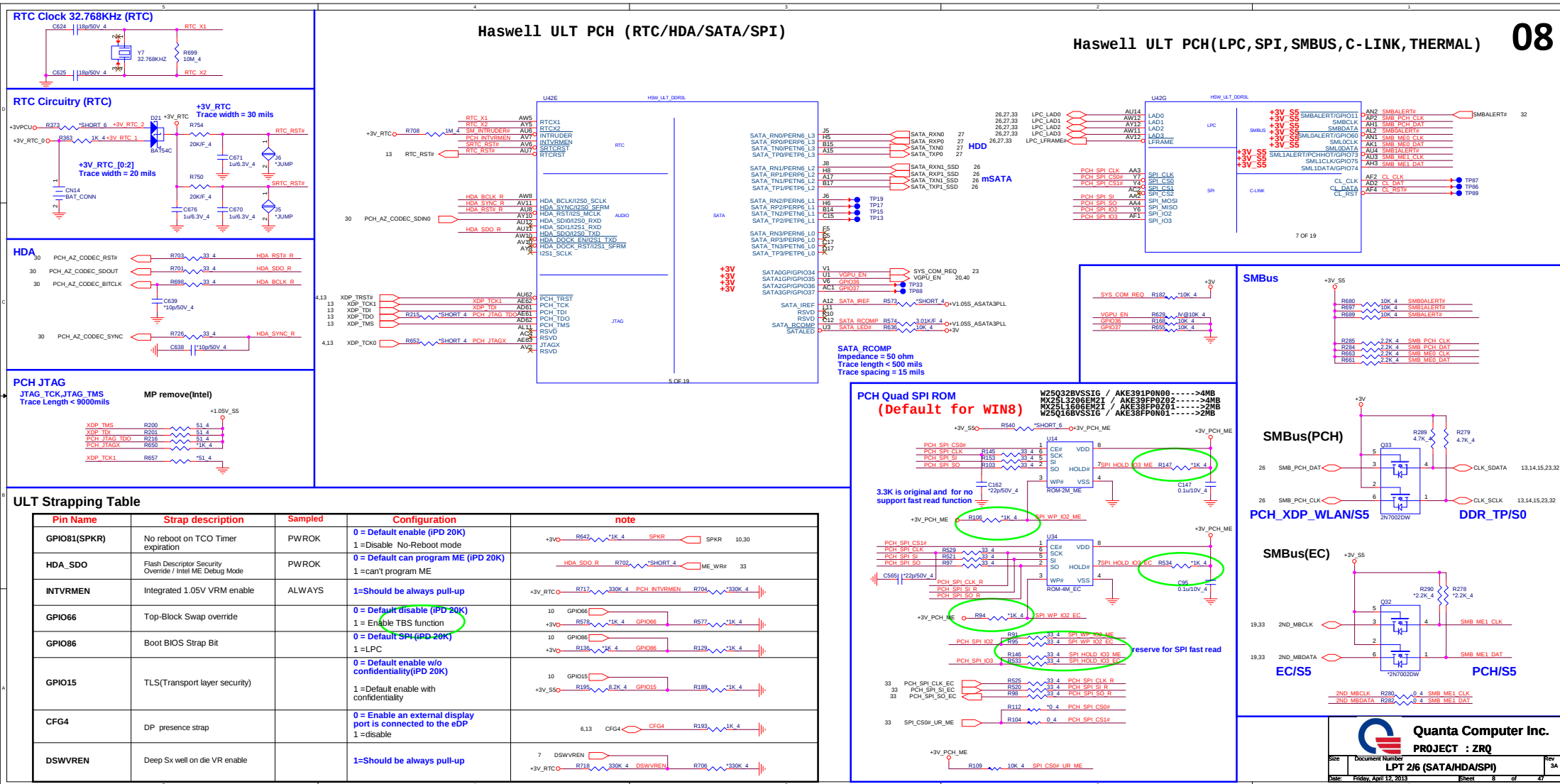


Quanta Computer Inc.
PROJECT : ZRQ

Size	Document Number	Rev
	LPT 1/6 (DMI/FDI/VGA)	3A
Date:	Friday, April 12, 2013	Sheet 7 of 47

Haswell ULT PCH(LPC, SPI, SMBUS, C-LINK, THERMAL)

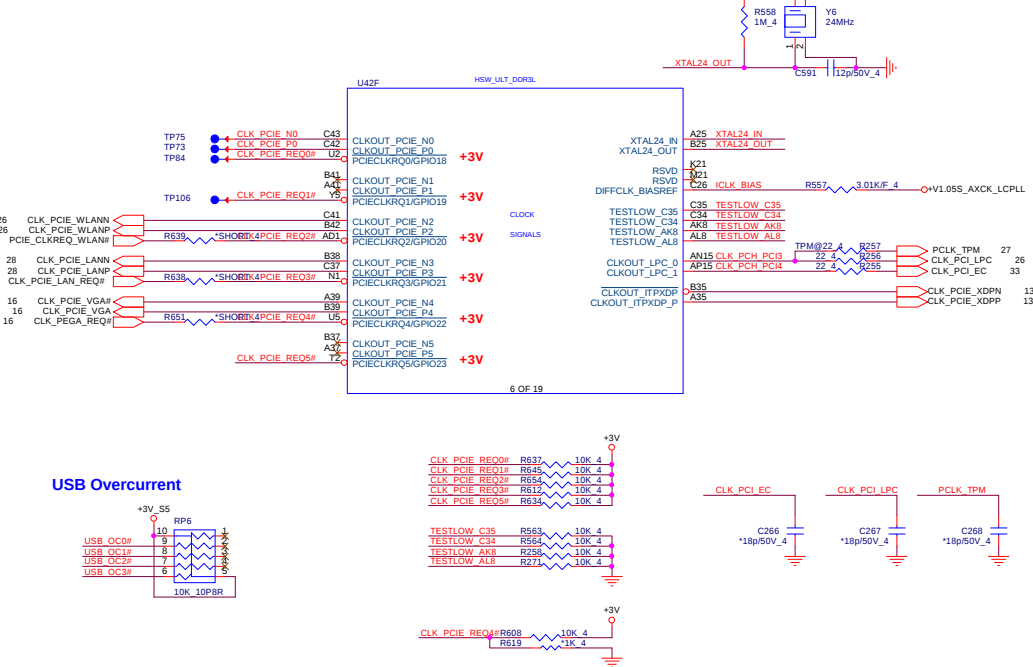
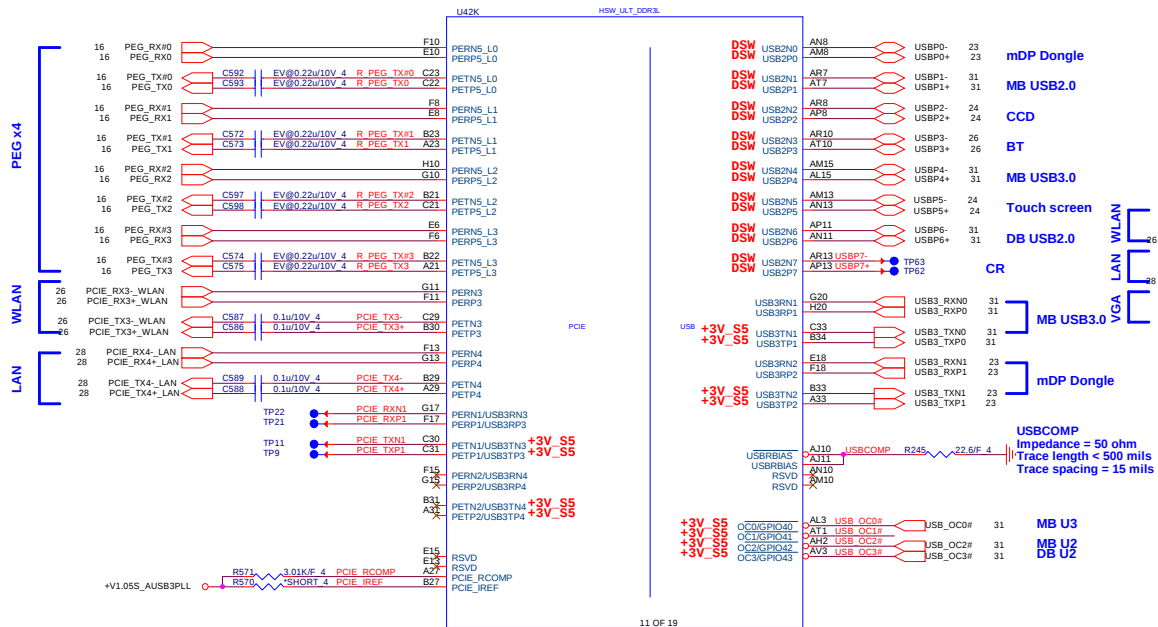
Haswell ULT PCH (RTC/HDA/SATA/SPI)



Haswell ULT PCH (PCIE,USB3.0,USB2.0)

Haswell ULT PCH (CLOCK)

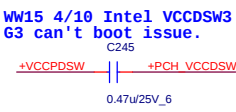
09



10

GPI027 : If not used then use
8.2-k Ω to 10-k Ω pull-down to GND.

Size	Document Number	Rev
	LPT 4/6 (GPIO/MISC)	3A
Date:	Friday, April 12, 2013	Sheet 10 of 47



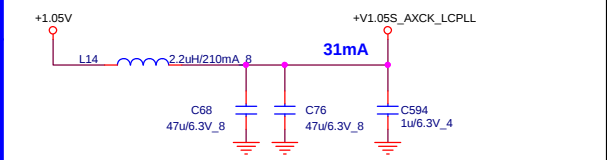
11mA

+3V_S5 +V3.3DX_1.5DX_1.8DX_AUDIO

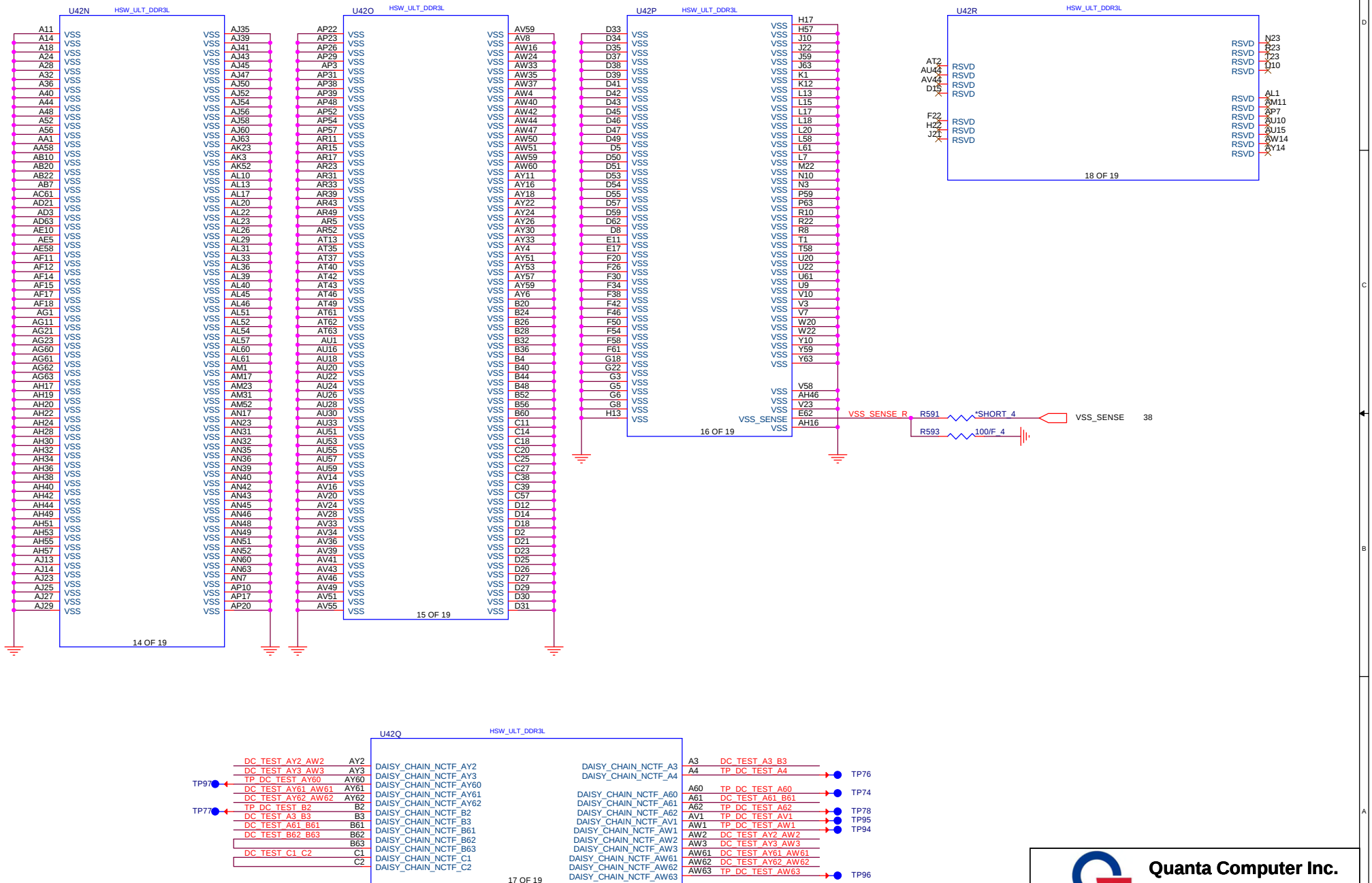
R252 *SHORT 6

C234
0.1u/10V_4

Place close to ball



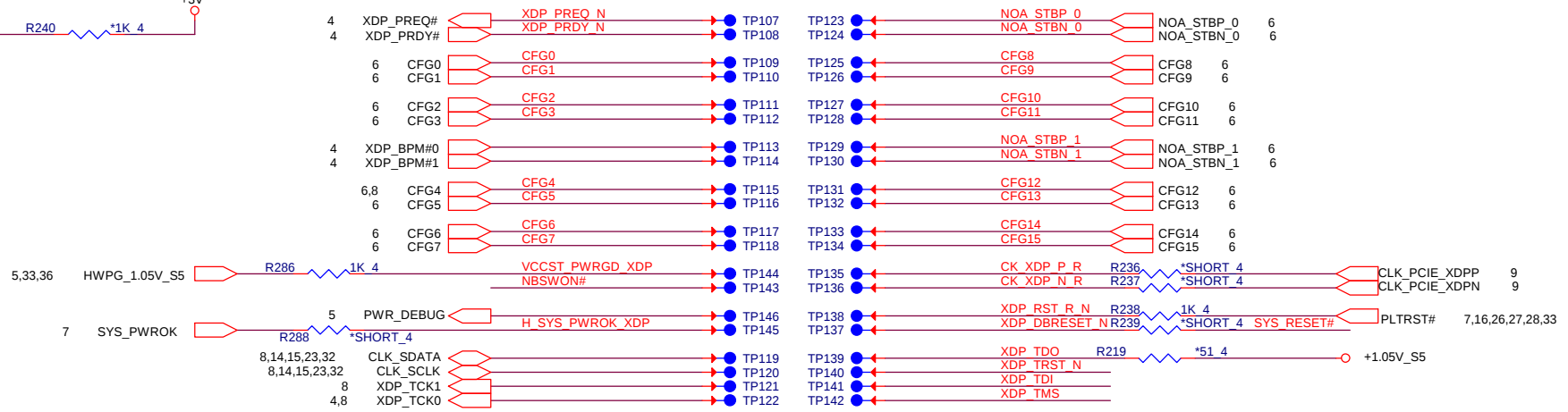
Haswell ULT (GND)



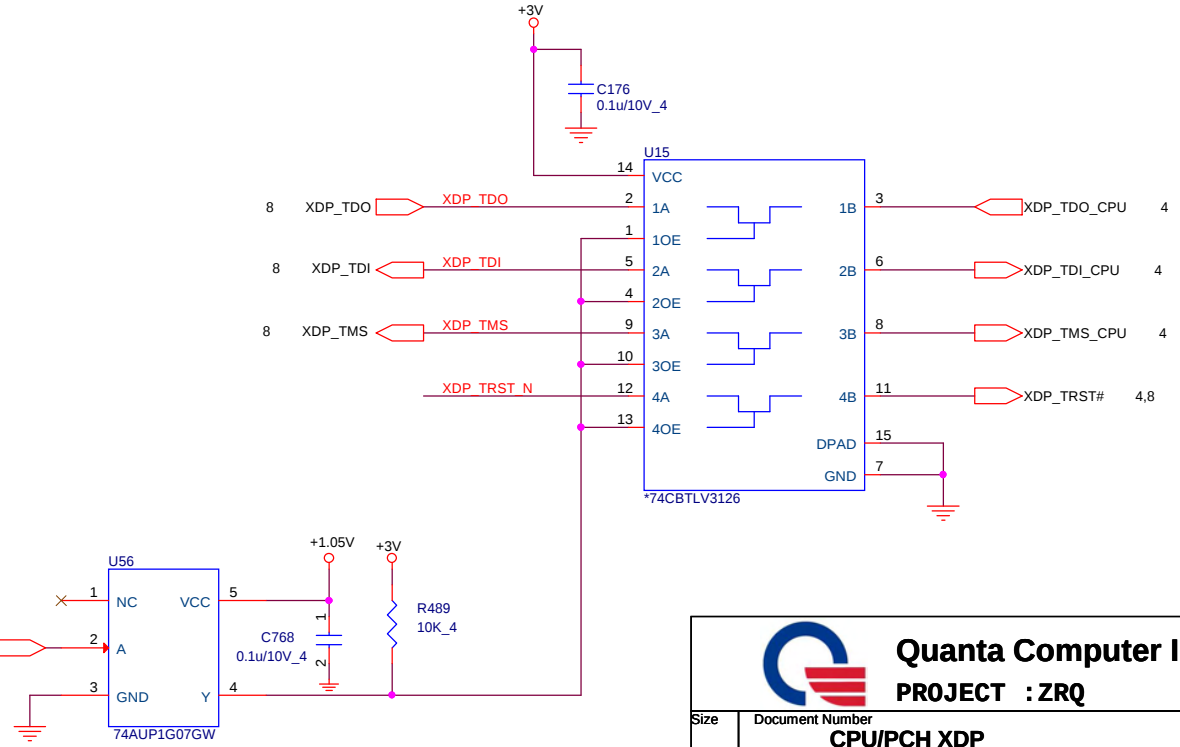
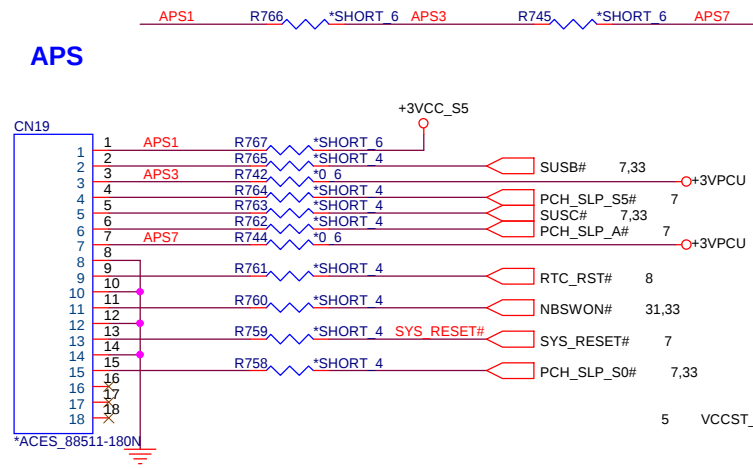
Quanta Computer Inc.
PROJECT : ZRQ

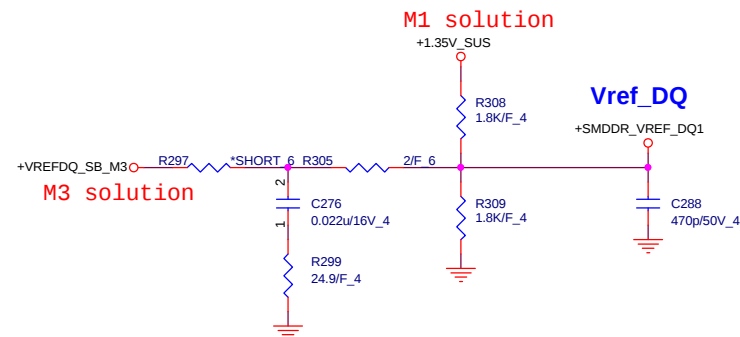
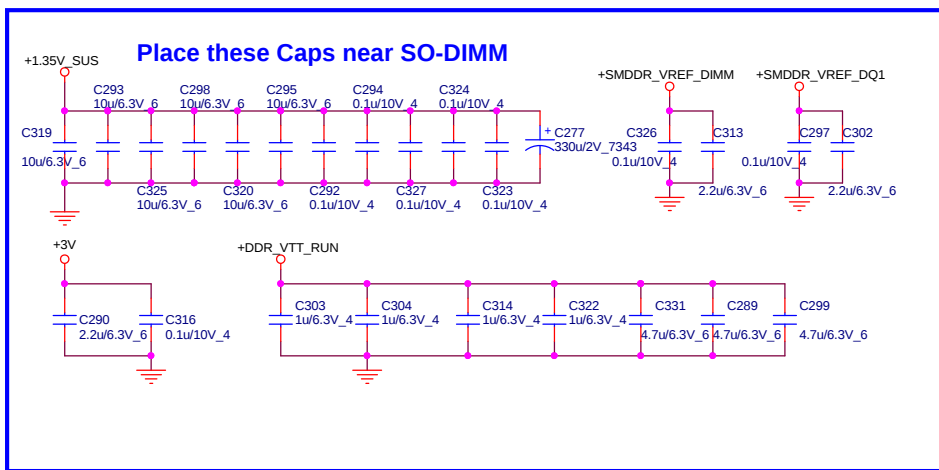
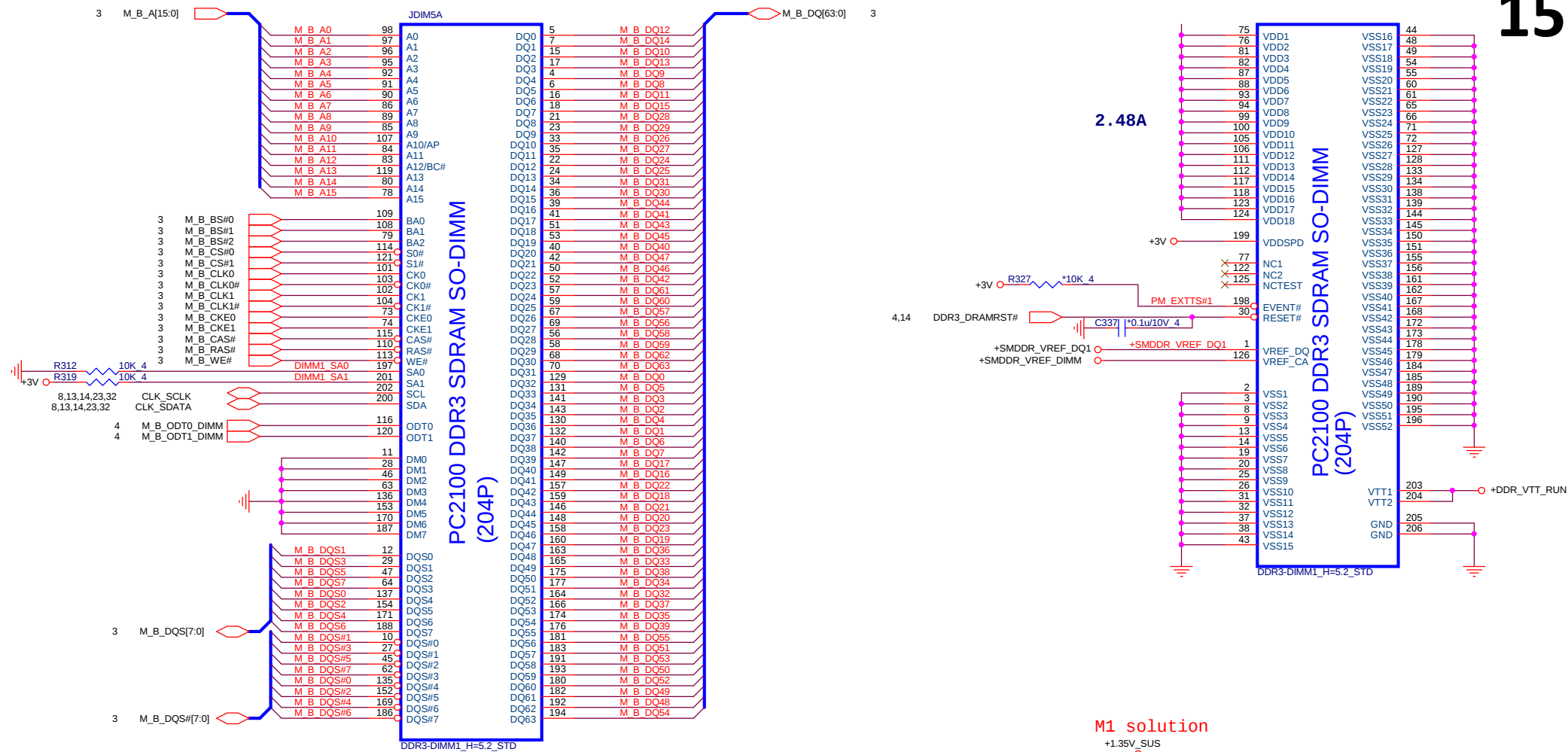
H_SYS_PWROK_XDP R287 *1K 4 +3V_S5

XDP_DBRESET_N R240 *1K 4 +3V



APS





Quanta Computer Inc.
PROJECT : ZRQ

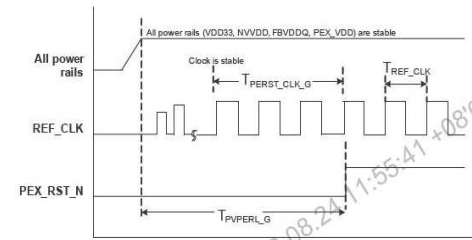
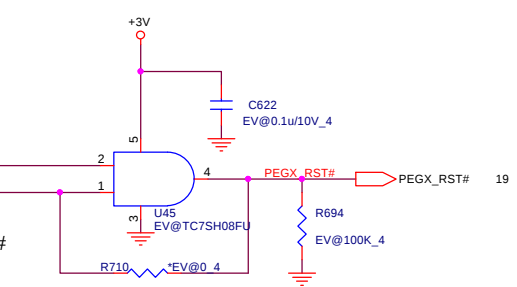
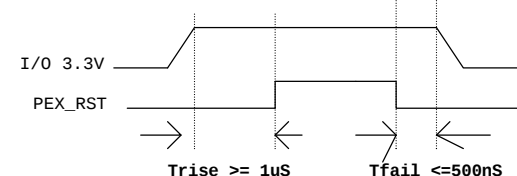


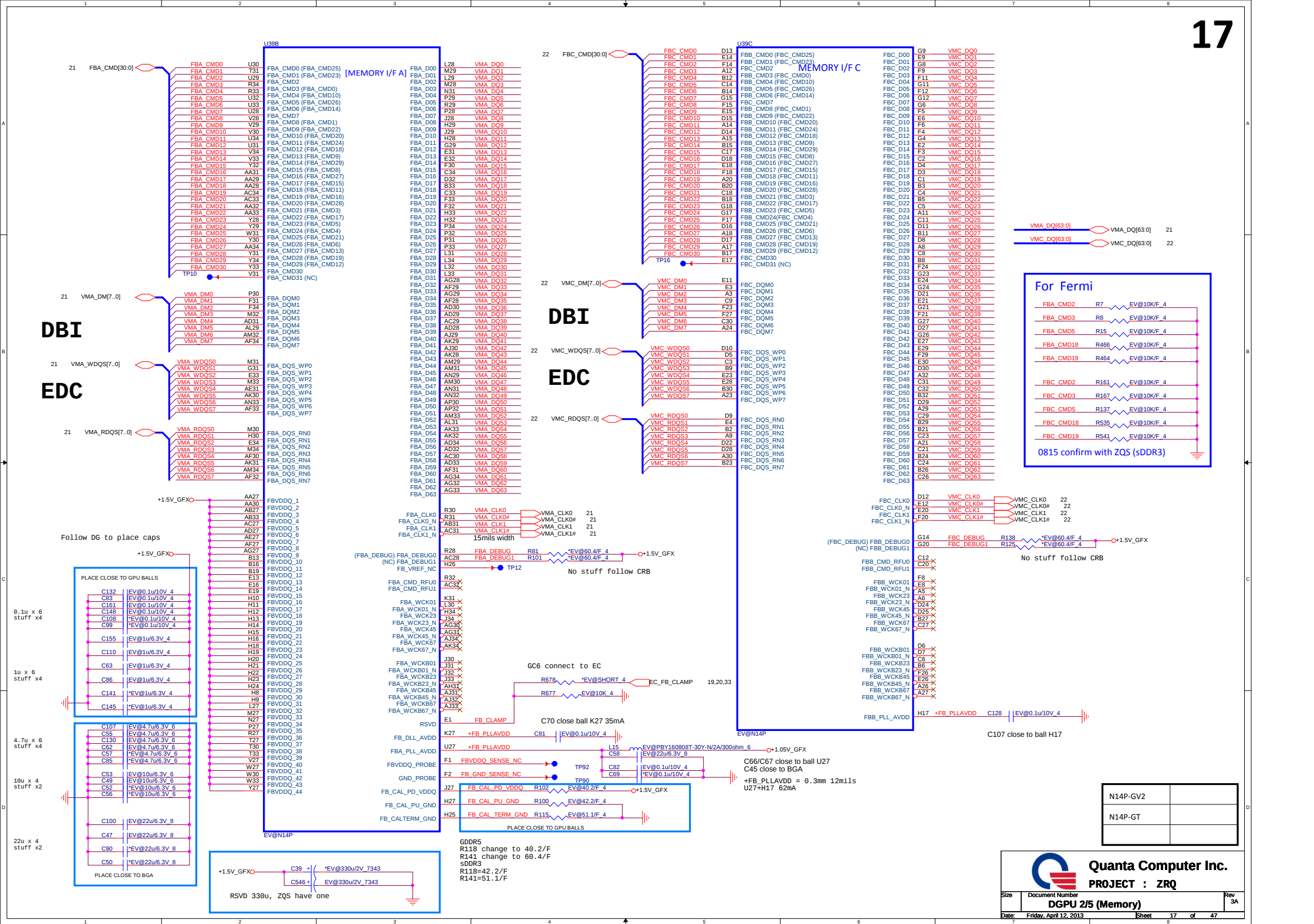
Table 3-8. N11x Reset Requirements for PCI Express 2.0

Constraint Parameter	Requirement	Notes
T _{FVPERL_G}	T _{FVPERL_G} ≥ 1μs	
T _{FPER1_CLK_G}	T _{FPER1_CLK_G} ≥ 1T _{REF_CLK}	

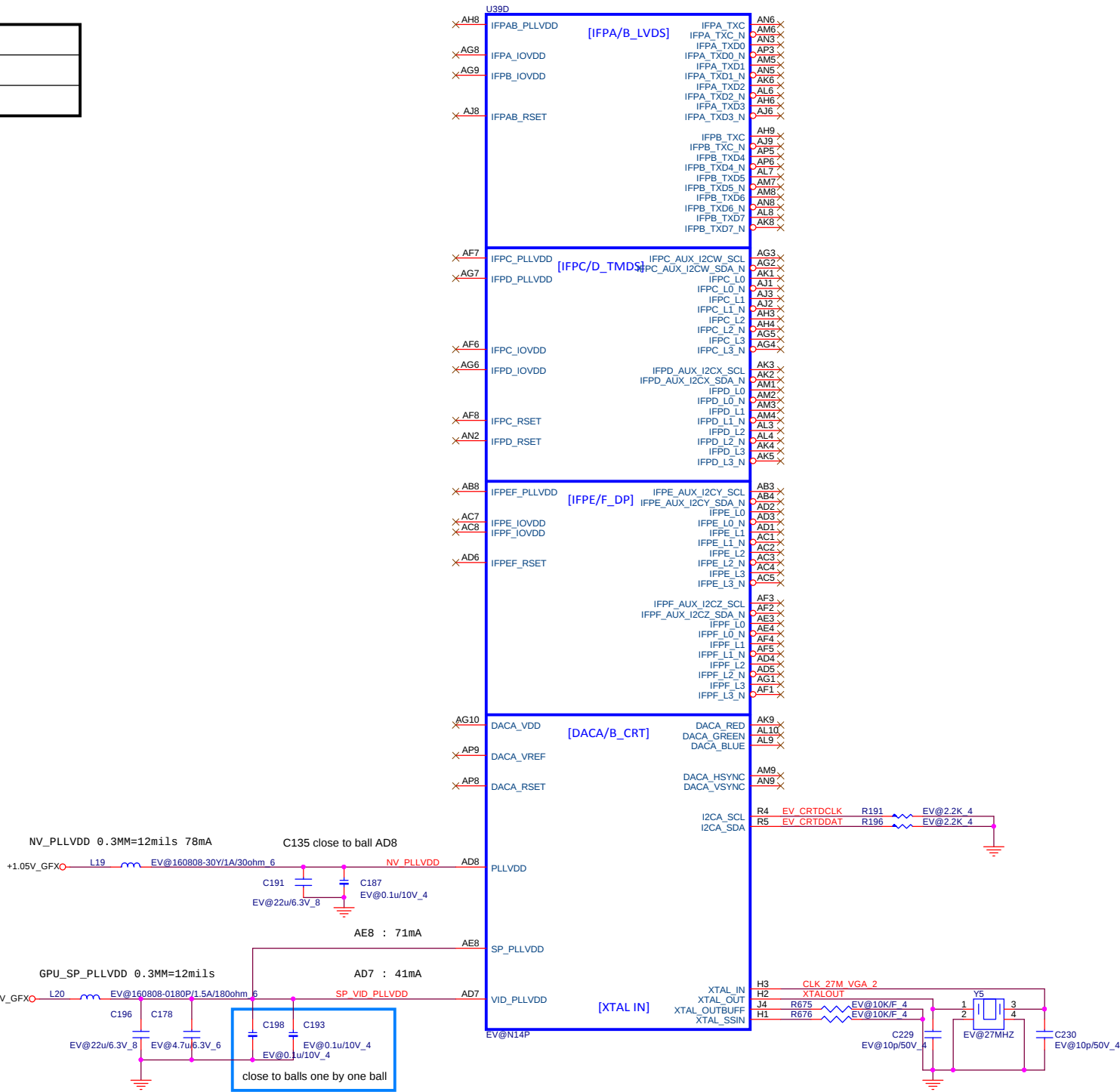


PEX_RST timing





N14P-GV2	
N14P-GT	



M_SI - MEMORY STRAP
M_SO - 5K pull high

RAP 0 - 45k pull high
RAP 1 - 5K pull down
RAP 3 - 5k pull down

or N14P-GT sku
14P-GT device ID=0x0FE4
ROM_SCLK =15K pull down
STRAP2 =25K pull down
STRAP4 = 45k Pull down

N14P-GV2 sku
14P-GV2 QS device ID=0x
ROM_SCLK =5K pull high
STRAP2= 15k pull down
STRAP4=45 pull down
For N14P-GV2 QS

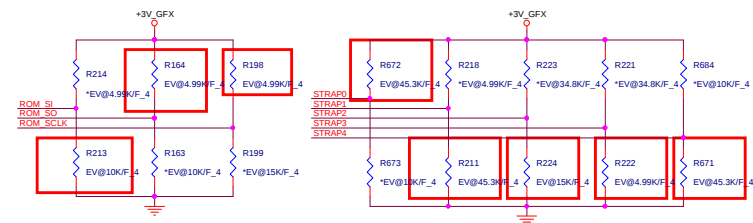
14P-GV2 ES device ID=0x
ROM_SCLK =15K pull down
STRAP2= 30k pull high
STRAP4=10K pull down
For N14P-GV2 ES

Logical Strap Bit Mapping		
	PU-VDD	PD
4.99K	1000	0000
10K	1001	0001
15K	1010	0010
20K	1011	0011
24.9K	1100	0100
30.1K	1101	0101
34.8K	1110	0110
45.3K	1111	0111

STRAP3 Optimus ----> 4.99k PD Discrete only ----> 15K PD
Resistor P/N 4.99K----> CS24992FB26 10K ----> CS31002FB26 15K ----> CS31502FB24 20K ----> CS32002FB29 24.9K----> CS32492FB16 30.1K----> CS33012FB18 34.8K----> CS33482FB22 45.3K----> CS34532FB18

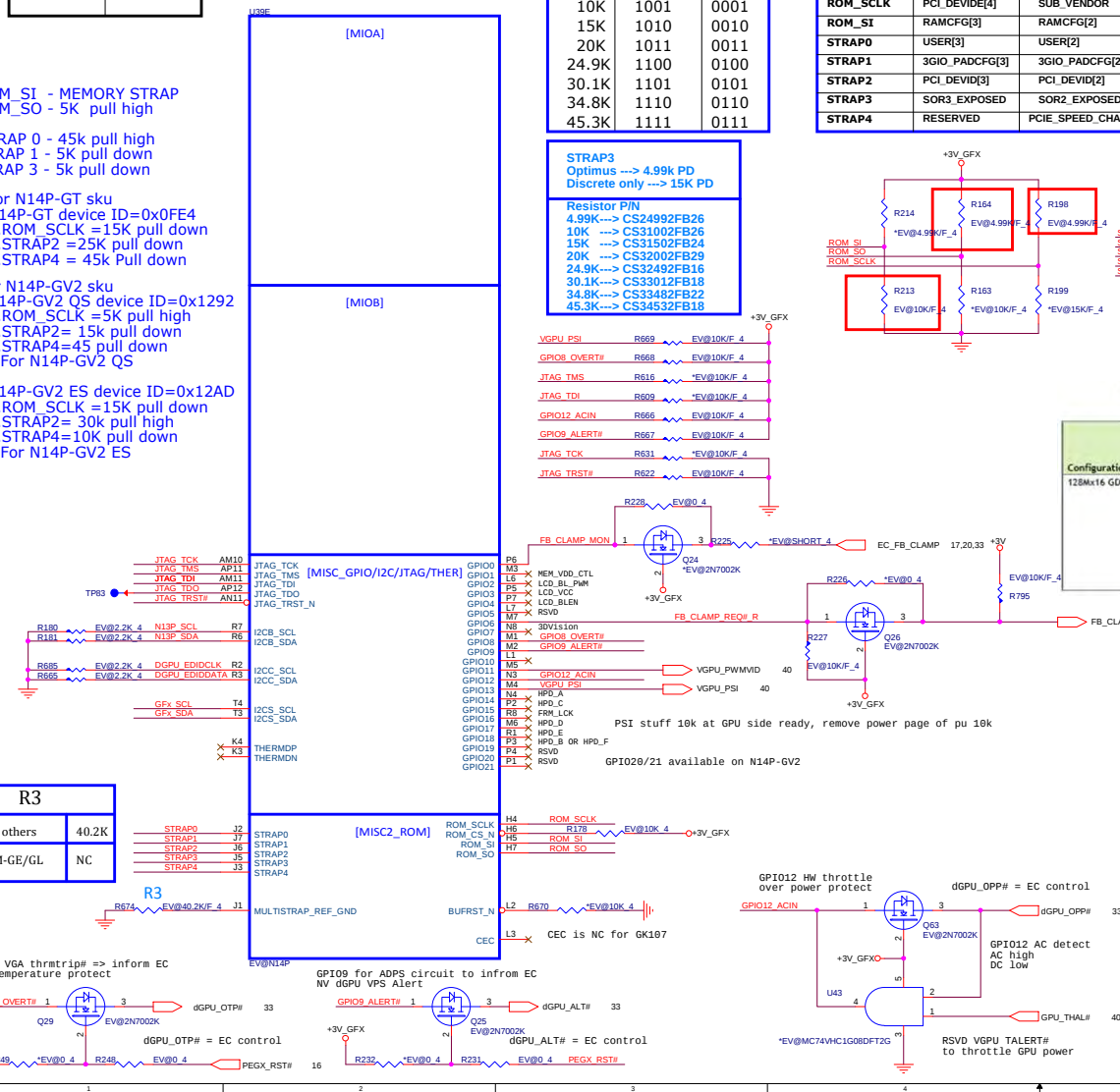
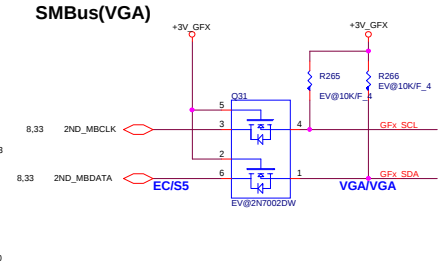
	Logical Strapping Bit3	Logical Strapping Bit2	Logical Strapping Bit1	Logical Strapping Bit0	
ROM_SO	FB_1	FB_0	SMB_ALT_ADDR	VGA_DEVICE	1000
ROM_SCLK	PCI_DEVIDE[4]	SUB_VENDOR	PCI_DEVIDE[5]	PEX_PL_LN_TERM	0010
ROM_SI	RAMCFG[3]	RAMCFG[2]	RAMCFG[1]	RAMCFG[0]	XXXX
STRAP0	USER[3]	USER[2]	USER[1]	USER[0]	1111
STRAP1	3GIO_PADCFG[3]	3GIO_PADCFG[2]	3GIO_PADCFG[1]	3GIO_PADCFG[0]	0000
STRAP2	PCI_DEVID[3]	PCI_DEVID[2]	PCI_DEVID[1]	PCI_DEVID[0]	0100
STRAP3	SOR3_EXPOSED	SOR2_EXPOSED	SOR1_EXPOSED	SOR0_EXPOSED	0000
STRAP4	RESERVED	PCIE_SPEED_CHANGE_GEN3	PCIE_MAX_SPEED	DP_PLL_VDD33	0111

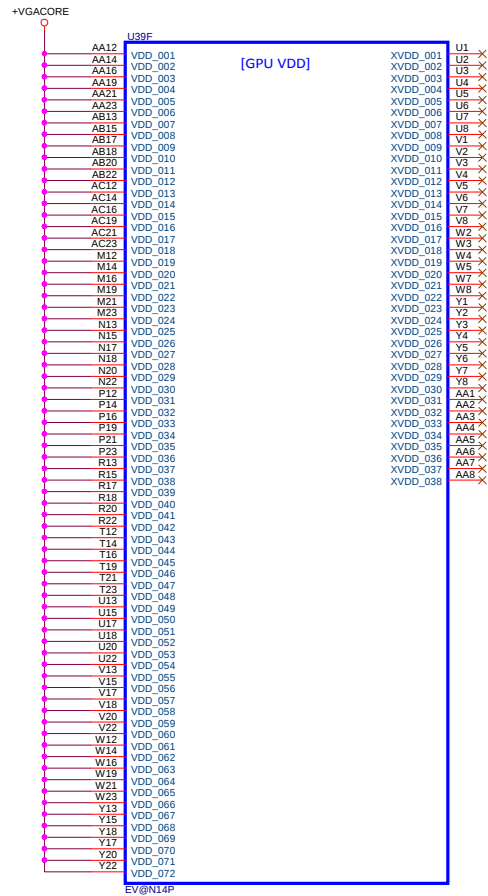
	ROM_SI	ROM_SO	ROM_SCLK	STRAP0	STRAP1	STRAP2	STRAP3	STRAP4
N14P_GV	L_10K	H_4.99K	H_4.99K	H_45.3K	L_45.3K	L_15K	L_4.99K	L_45.3K
N14P_GE	L_10K	L_10K	L_10K	H_10K	H_10K	L_10K	L_10K	L_10K
N14P_GT	L_10K	H_4.99K	L_15K	H_45.3K	L_4.99K	L_24.9K	L_4.99K	L_45.3K

Table 9. N14P-GV/GT/GS/LP/GE GDDR5 Recommended Memories
128Mx16 Configuration

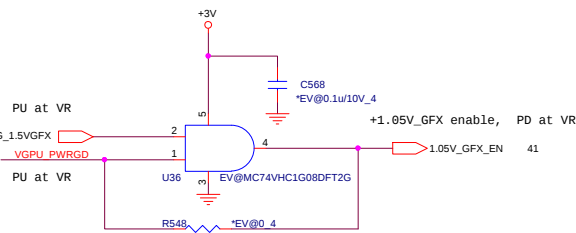
Configuration	Vendor	Strap	FBVDD/ FBVDDQ	Manufacturer Part Number	Max Speed WCR (MHz)	Memory Date Code Minimum	Status
128Mx16 GDDR5	Hynix	0x4	1.5 V/ 1.5 V	H5GQ2H244FR-T2C	2500	11/A	Production Candidate
		0x6	1.35V/ 1.35V	H5GQ2H244FR-T2C	2000	11/A	Production Candidate
	SamSung	0x5	1.5 V/ 1.5 V	K4G20325FD-FC04	2500	1219	Production Candidate
		0x7	1.35V/ 1.35V	K4G20325FD-FC04	2000	1219	Production Candidate

Vendor	P/N	Mfr. P/N	ROM_Si
Hynix	AKG5MwUTW13	H5GQ2H24AFR-T2C	0100
Samsung		K4G20325FD-FC04	0101

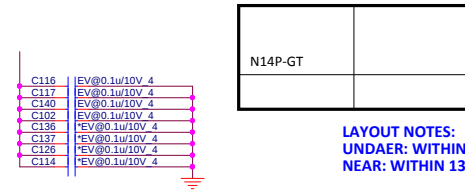
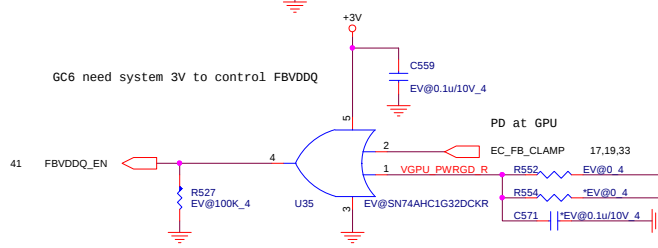




for meet Power down sequence
for +3V_GFX

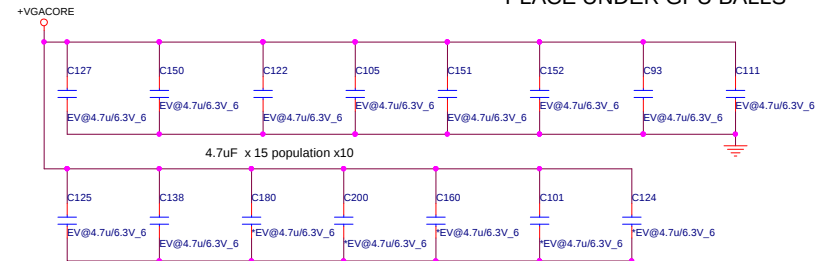


GC6 need system 3V to control FBVDDQ

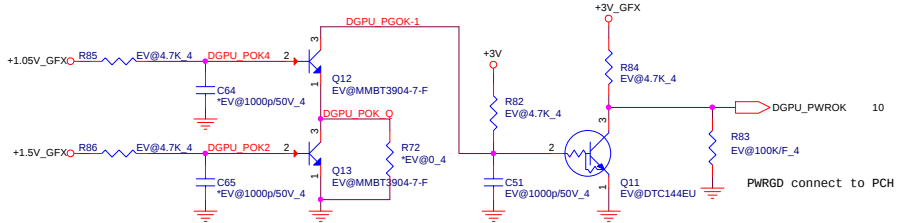
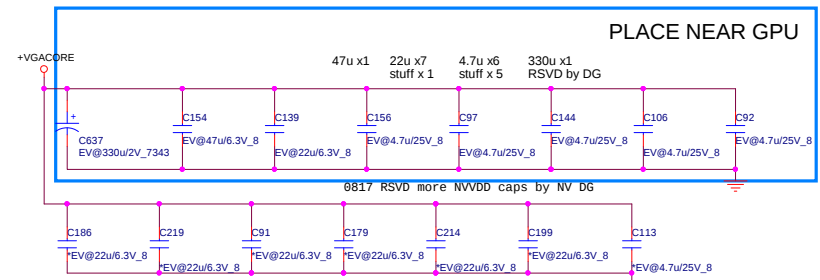


LAYOUT NOTES:
UNDAER: WITHIN 150MILS
NEAR: WITHIN 1378MILS

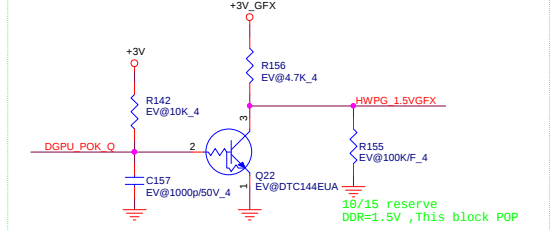
PLACE UNDER GPU BALLS



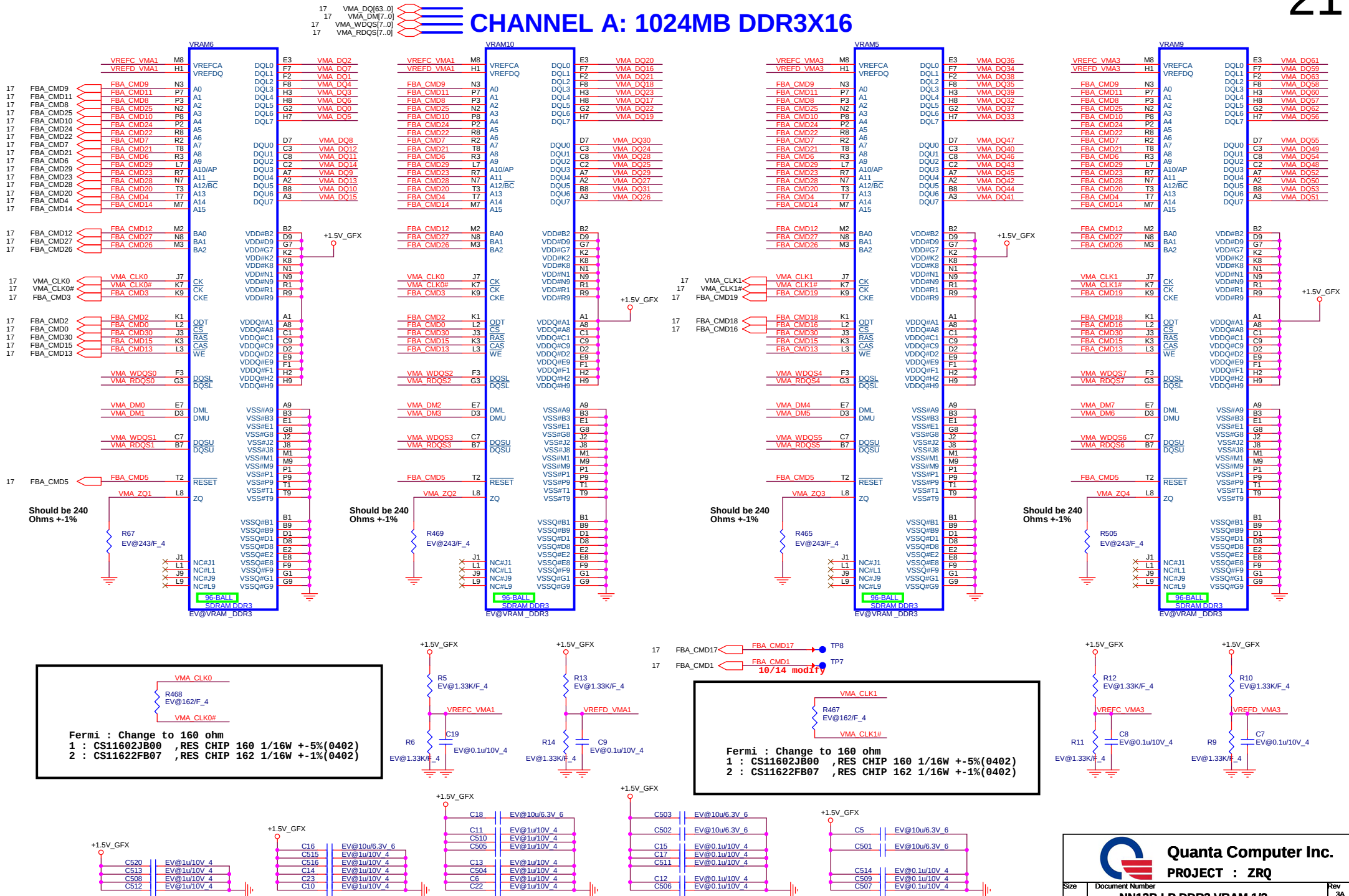
PLACE NEAR GPU



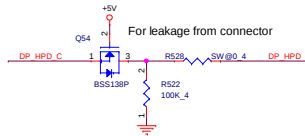
HWPQ_1.5VGFX for DDR=1.5V



CHANNEL A: 1024MB DDR3X16

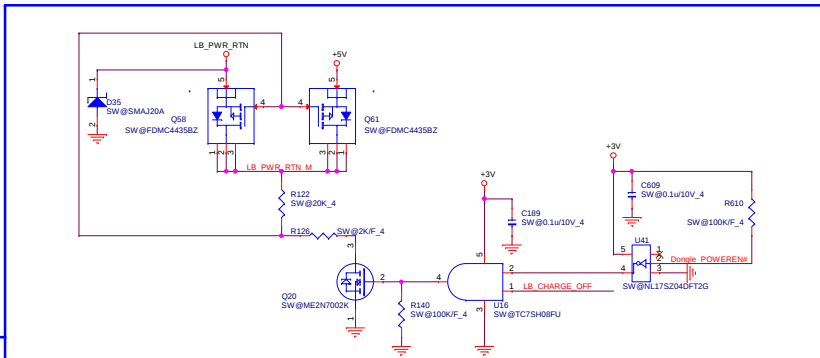
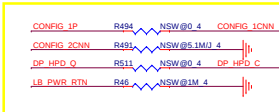
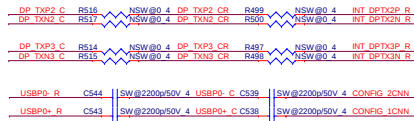




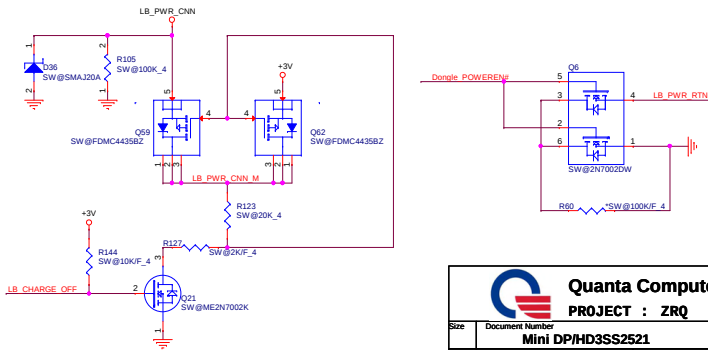
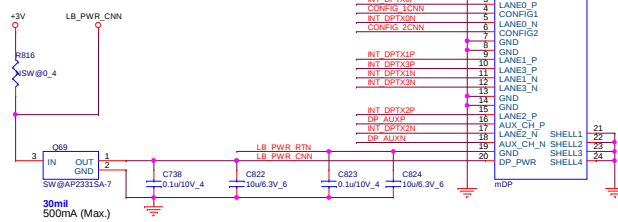


Four circuit diagrams are shown, each representing a switch connection to a specific pin:

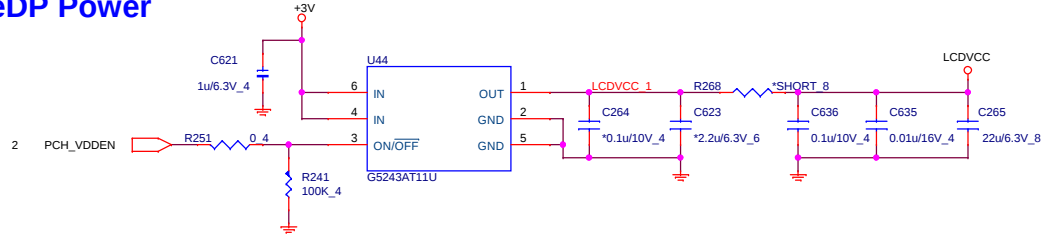
- Top diagram:** A 3V supply is connected to the top terminal of switch R510. The bottom terminal of R510 is connected to the USB2_SEL pin. The switch is labeled with its ID and the pin name.
- Second diagram:** A 3V supply is connected to the top terminal of switch R509. The bottom terminal of R509 is connected to the USB3_SEL pin. The switch is labeled with its ID and the pin name.
- Third diagram:** A 3V supply is connected to the top terminal of switch R76. The bottom terminal of R76 is connected to the USB2_MUX_DS pin. The switch is labeled with its ID and the pin name.
- Bottom diagram:** A 3V supply is connected to the top terminal of switch R78. The bottom terminal of R78 is connected to the USB3_MUX_DS pin. The switch is labeled with its ID and the pin name.

[illegible]

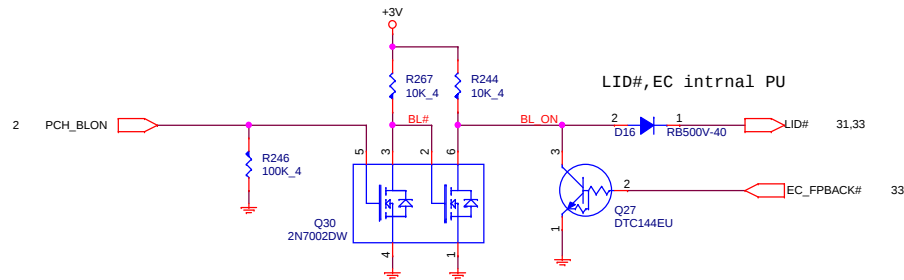
+3V LB_PWR_CI



eDP Power



Backlight Control



Lid Switch (HSR)(move to USB/B)

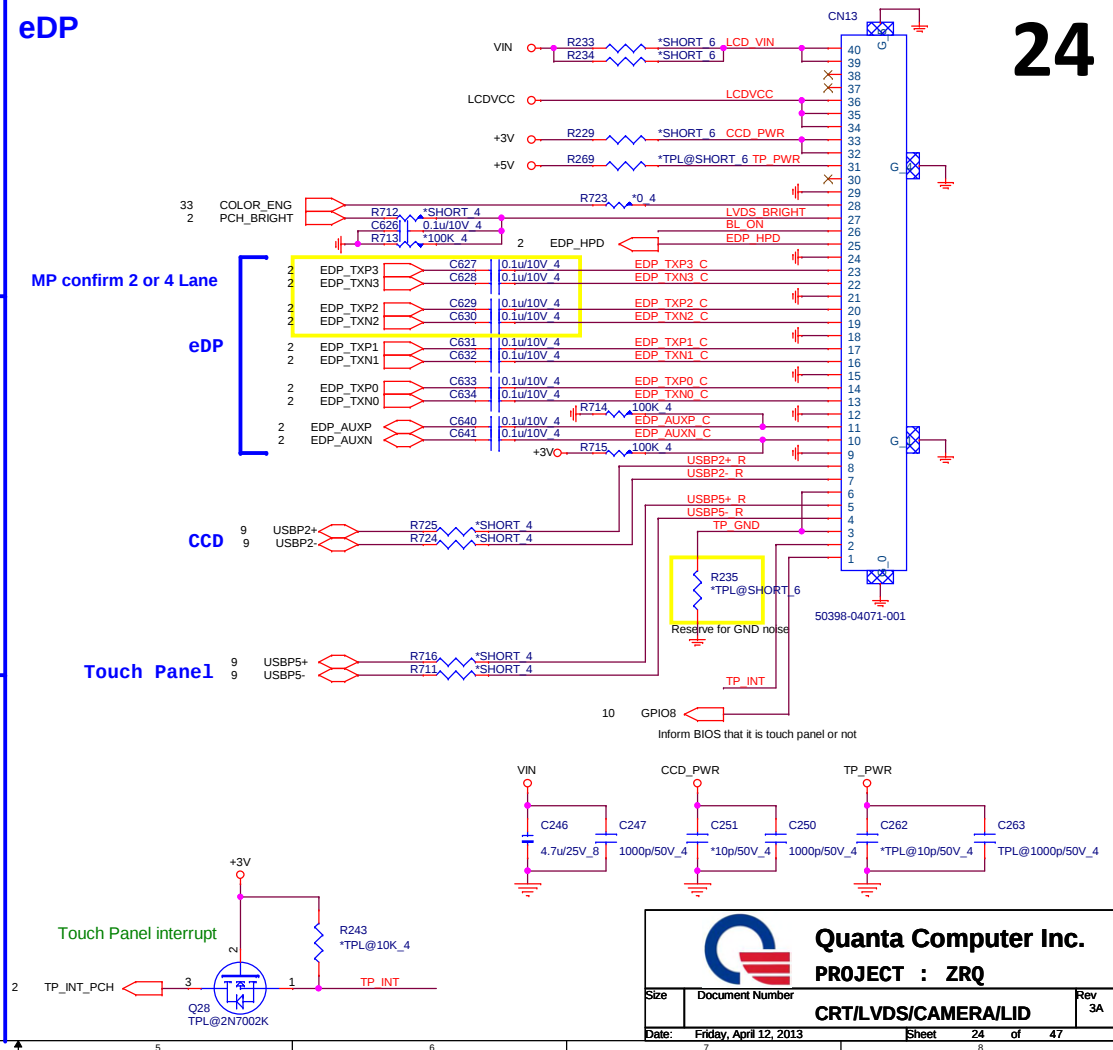
eDP

MP confirm 2 or 4 Lane

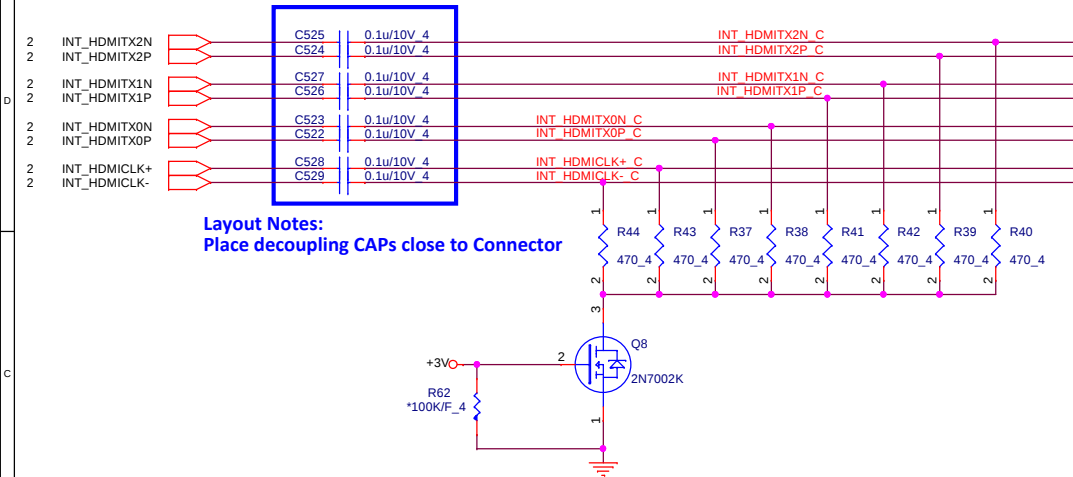
eDP

CCD

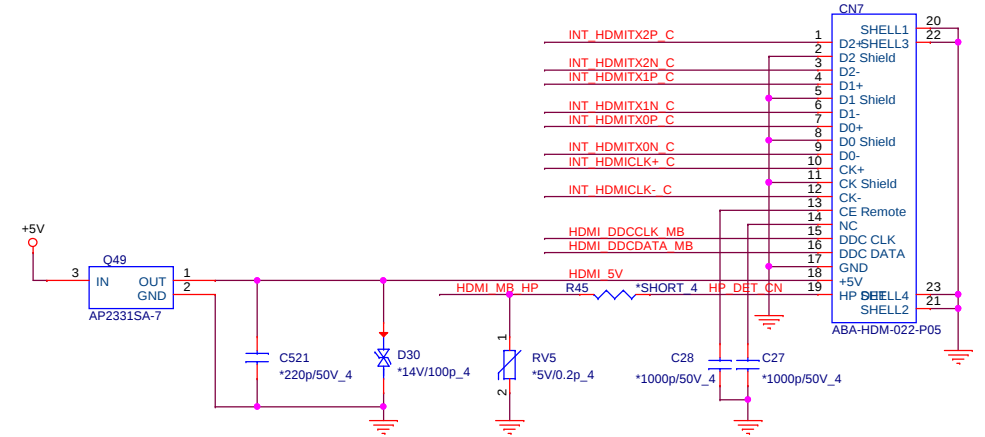
Touch Panel



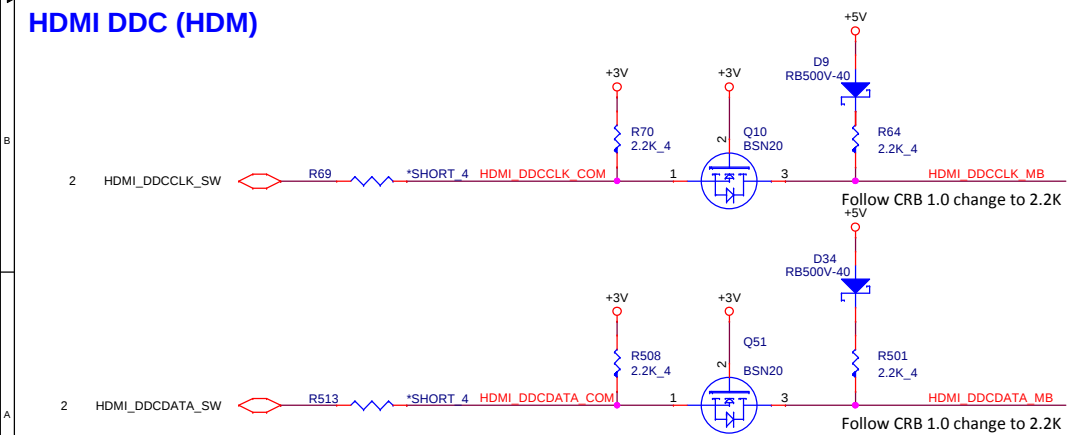
HDMI Cost Reduced level shift (HDM)



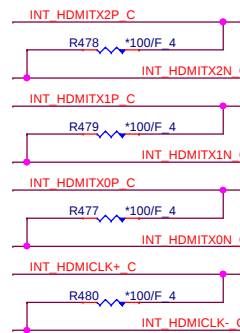
HDMI connector (HDM)



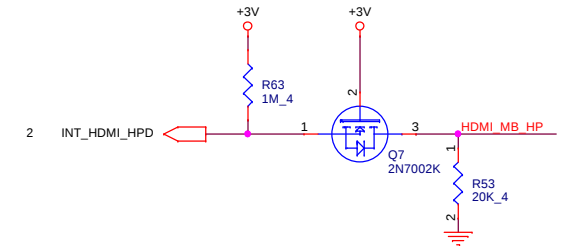
HDMI DDC (HDM)



EMI (EMC)



HDMI-detect (HDM)



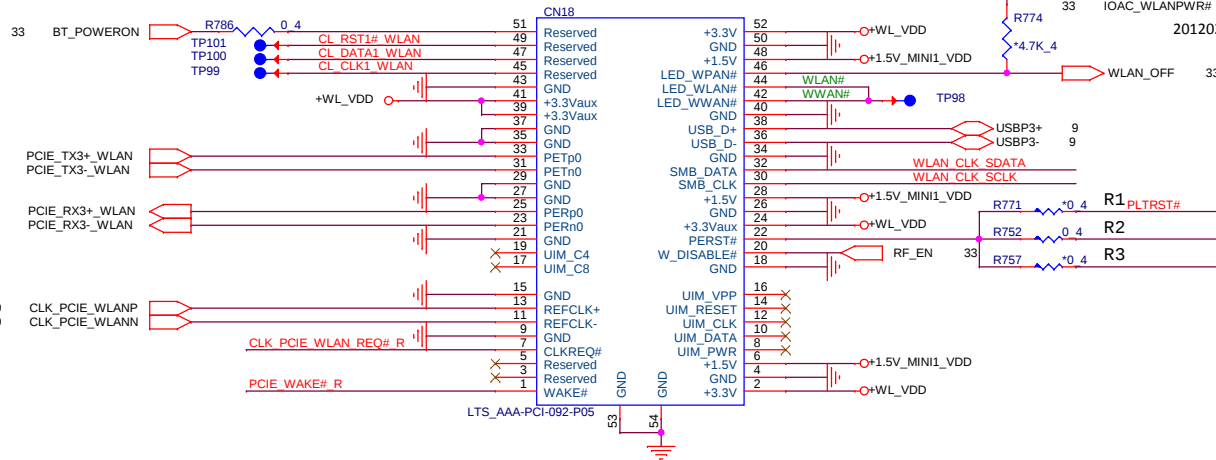
Quanta Computer Inc.
PROJECT : ZRQ

Size Document Number
HDMI (PS8101)
Date: Friday, April 12, 2013 Sheet 25 of 47 Rev 3A

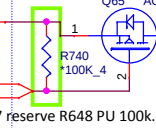
MINI-CARD WLAN(MPC)

+3.3V: 1000mA
+3.3Vaux:330mA
+1.5V:500mA

Check LED signal. (active high or low)
H=5.2mm

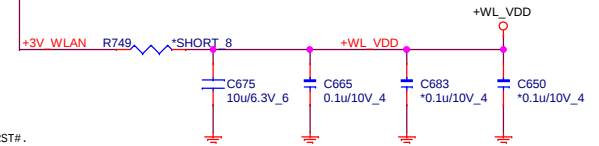


2011017 : stuff Q81 to enable wake function on WLAN for IOAC
check IOAC power rail can reduce Q81

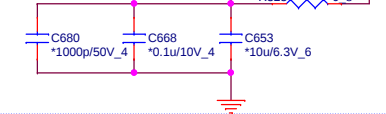


20111122 change to PMOS

Low	Mini card +3V power enable
High	Mini card +3V power disable



500mA for +1.5V

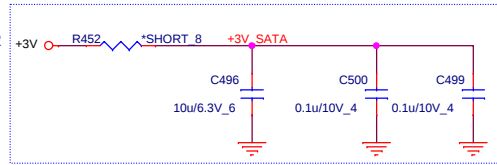


LAYOUT NOTE:
CLOSE TO CONNECTOR

mSATA(MNC)

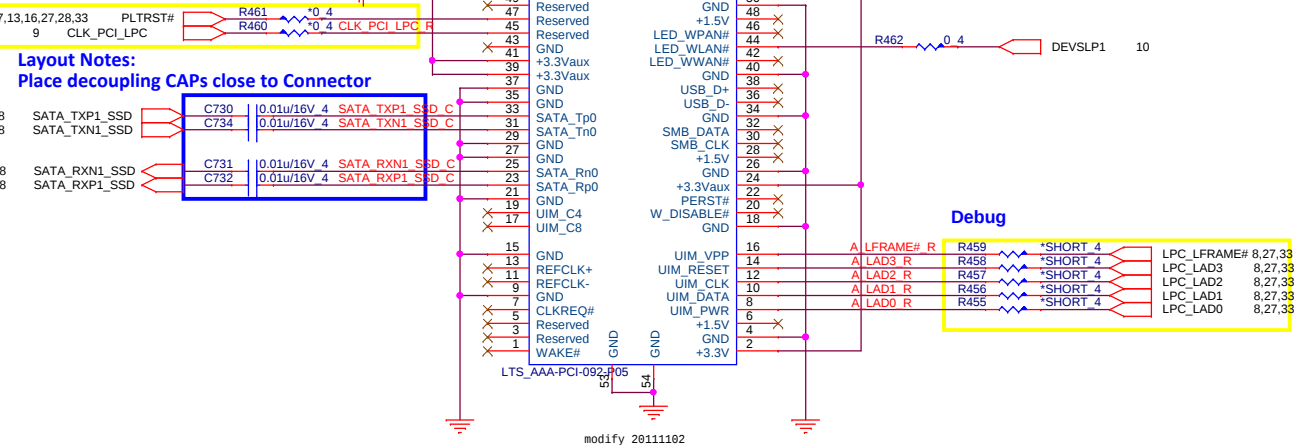
LAYOUT NOTE:
CLOSE TO CONNECTOR

rating = 1000mA @ 128G

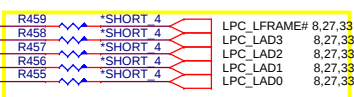


H=4.95mm

Debug



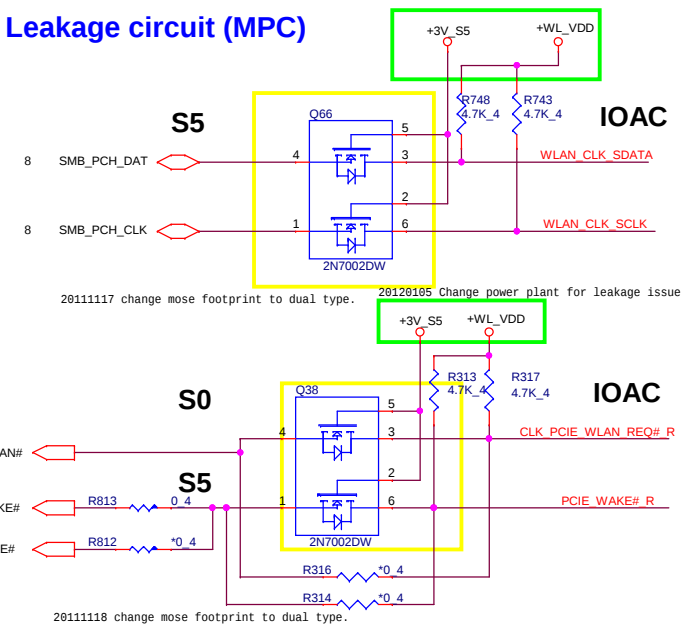
Debug



modify 20111102

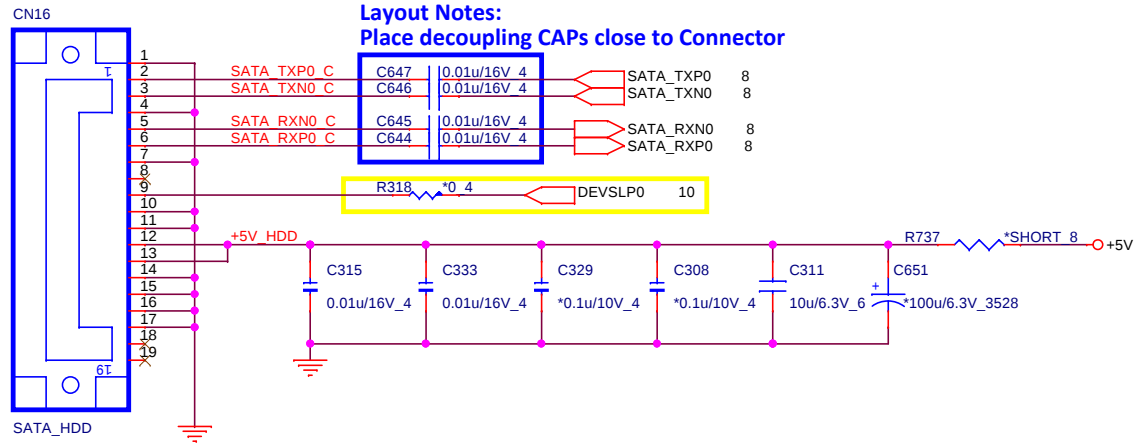
Leakage circuit (MPC)

20120105 change power plant for leakage issue.

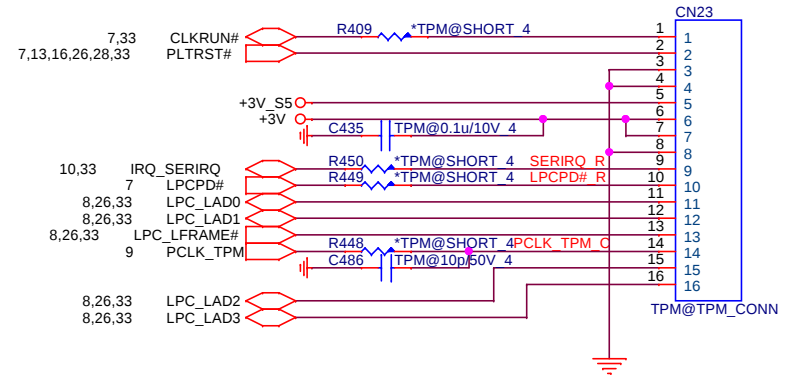


20111118 change mose footprint to dual type.

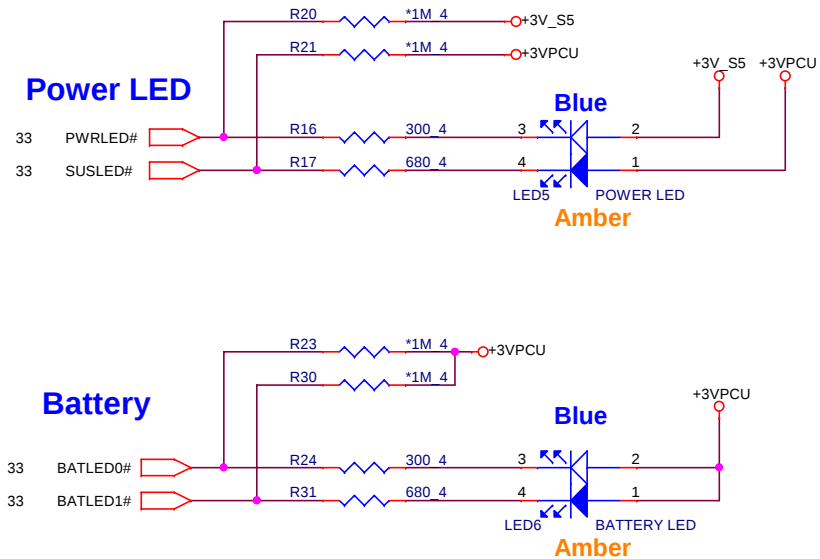
MAIN SATA HDD (HDD)



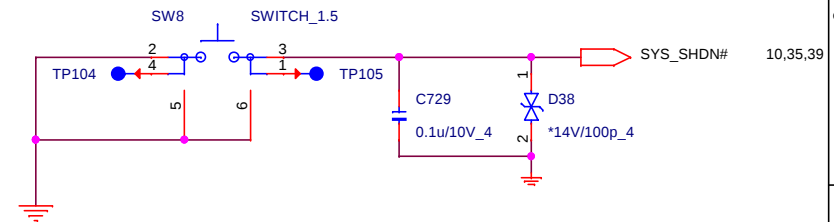
TPM (TPM)



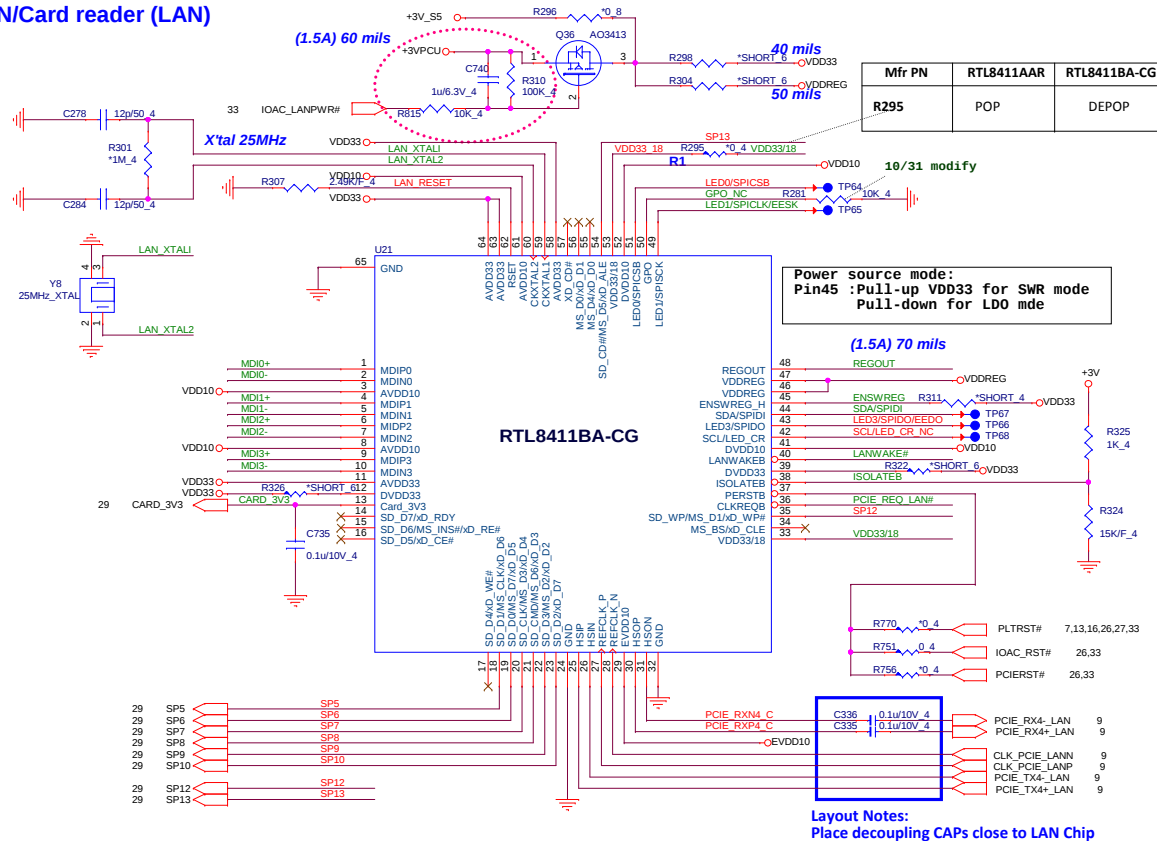
LED(UIF)



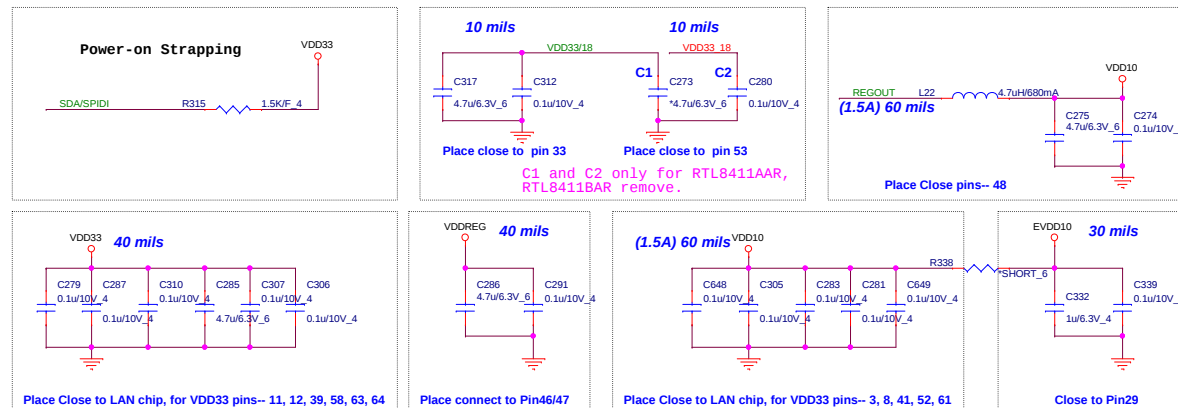
3/5VPCU reset switch (CLG)



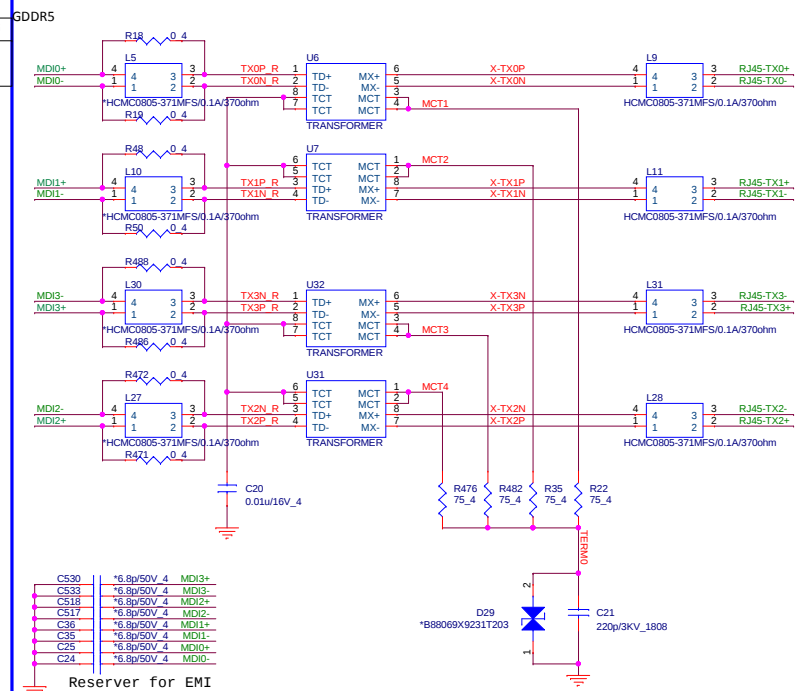
LAN/Card reader (LAN)



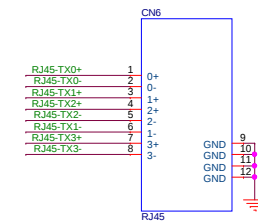
201201009: CLKREQ use S0 power domain by FAE



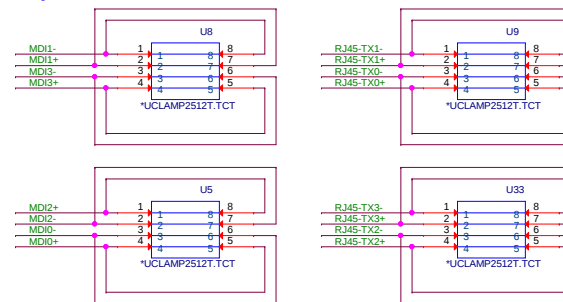
High Transformer (LAN)



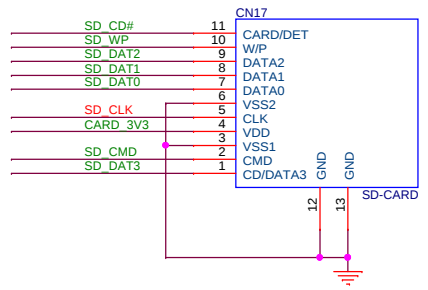
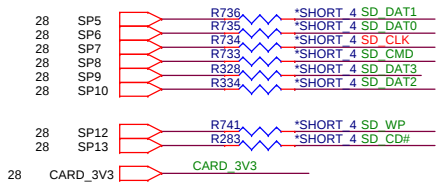
RJ45 CONNECTOR (LAN)



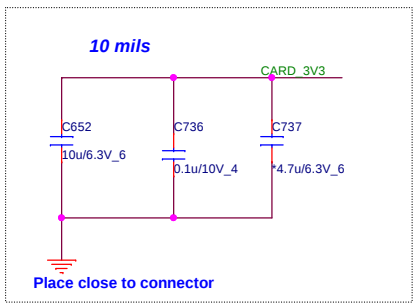
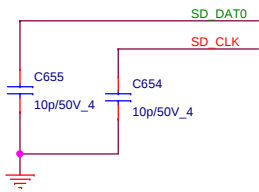
SURGE (LAN)



SD/MMC CARD READER CONNECTOR (MMC)



EMI

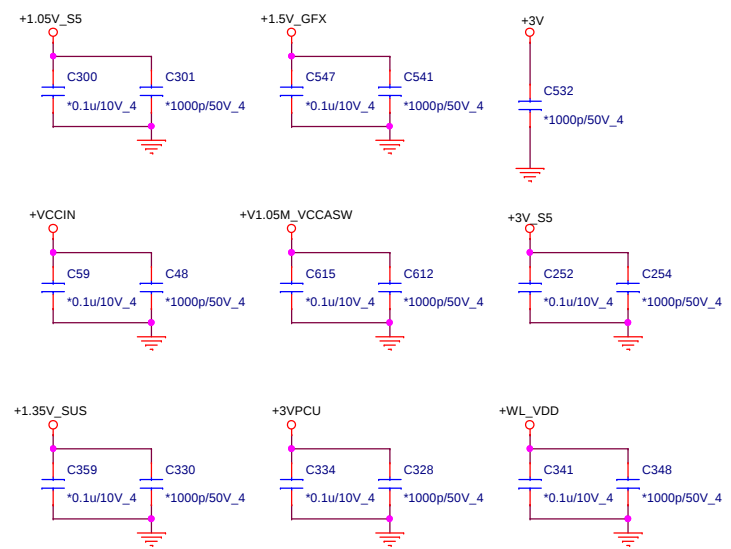


Share Pin

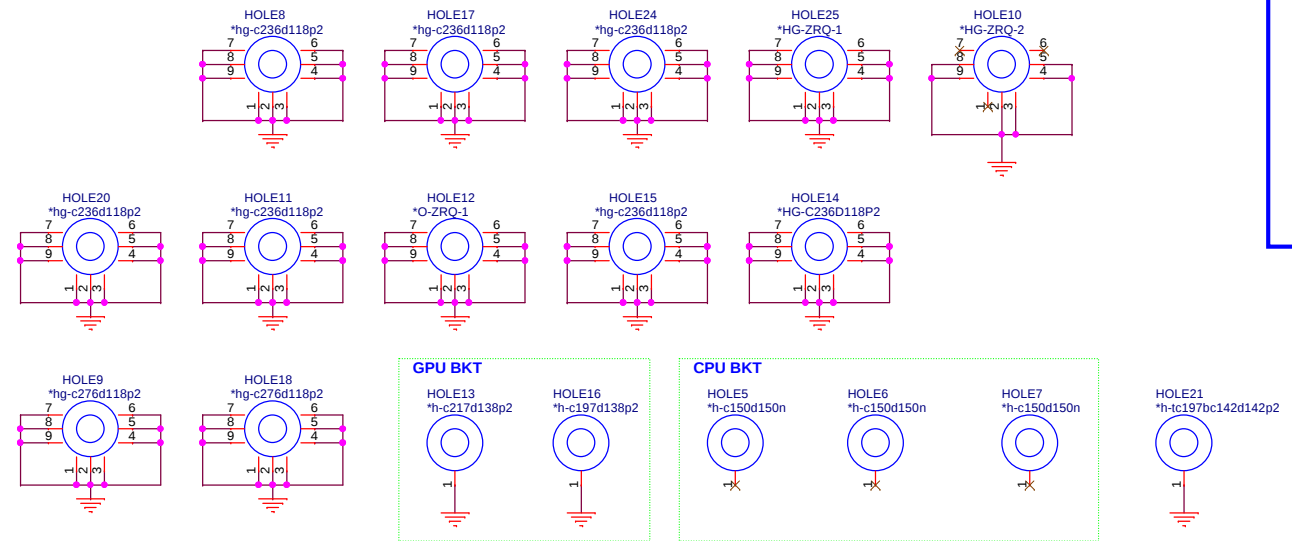
SP1	SD D7	xD RDY
SP2	SD D6	MS INS#
SP3	SD D5	xD CE#
SP4	SD D4	xD WE#
SP5	SD D1	MS CLK
SP6	SD D0	xD D5
SP7	SD CLK	MS D3
SP8	SD CMD	MS D6
SP9	SD D3	MS D2
SP10	SD D2	xD D7
SP11	MS BS	xD CLE
SP12	SD WP	MS D1
SP13	SD CD#	MS D5
SP14	MS D4	xD D9
SP15	MS D0	xD D1
SP16		xD CD#

Stitching cap (EMC)

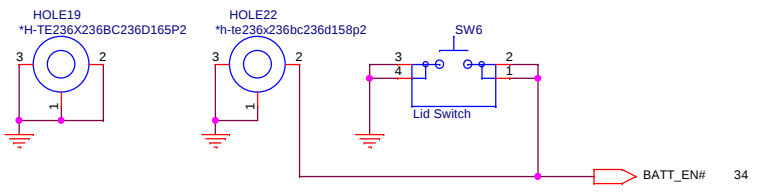
29



HOLE(OTH)



BATT Enable short pad



PAD5
*spad-e85x1268

Quanta Computer Inc.
PROJECT : ZRQ

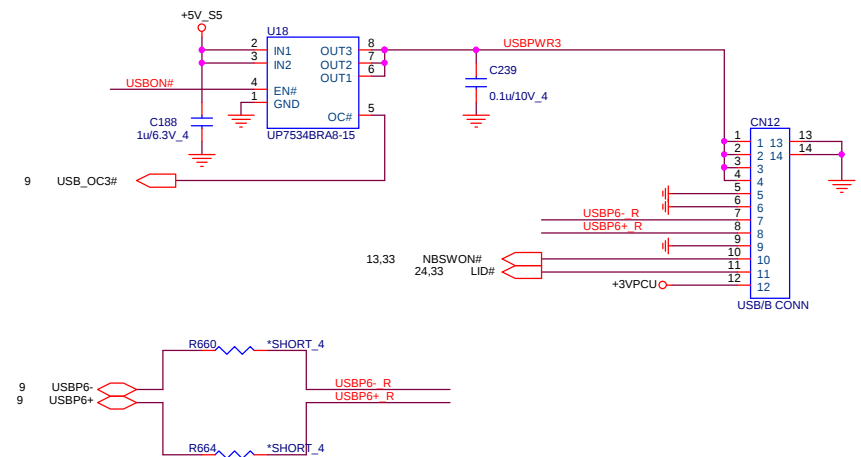
Size	Document Number	Rev
	CARD READER CONNECTOR	3A

Date: Friday, April 12, 2013 Sheet 29 of 47

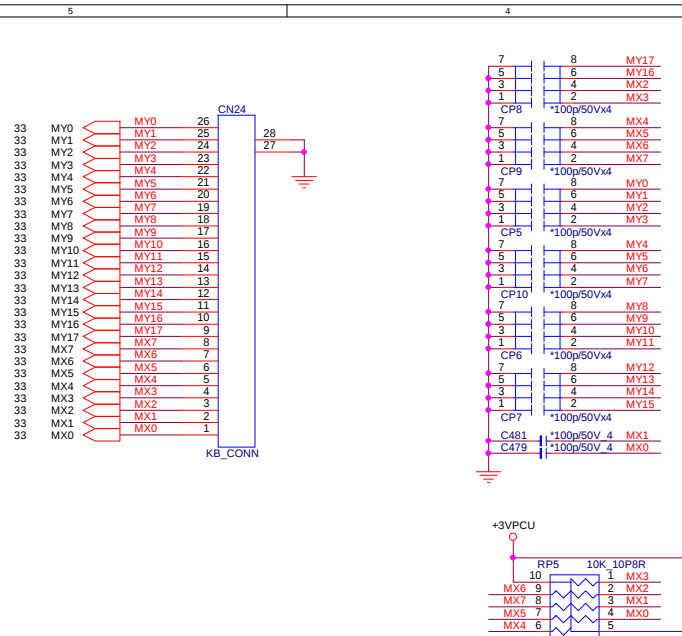
Active High:
1st: AL007534001 (Promate)
2nd: AL000547006 (GMT)
3rd: AL002511002 (DDS)



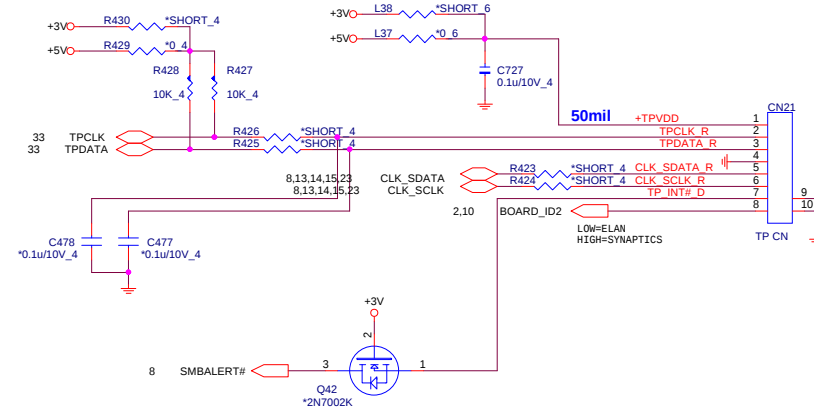
CB	SELCDP	Function
0	X	DCP autodetect with mouse/keyboard wakeup
1	0	SD charging with SDP only
1	1	SD charging with CDP or SDP only (depending on external device)



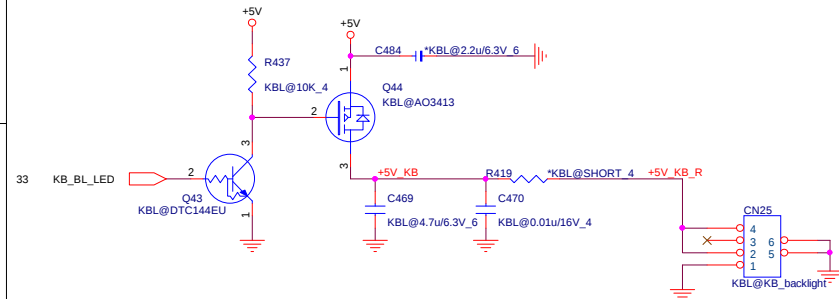
K/B (KBC)



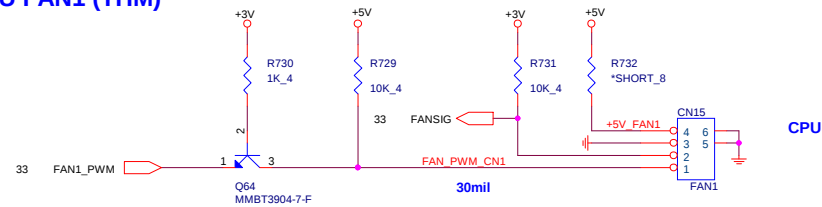
TOUCHPAD BOARD CONN (TPD)



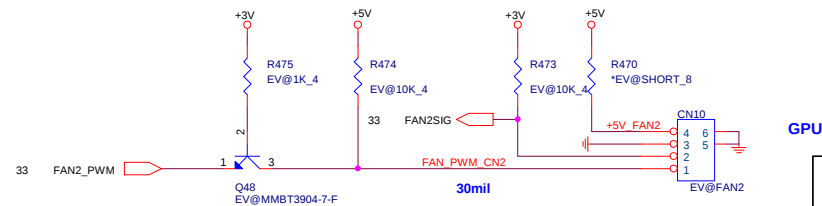
KB_BL LED (KBC)



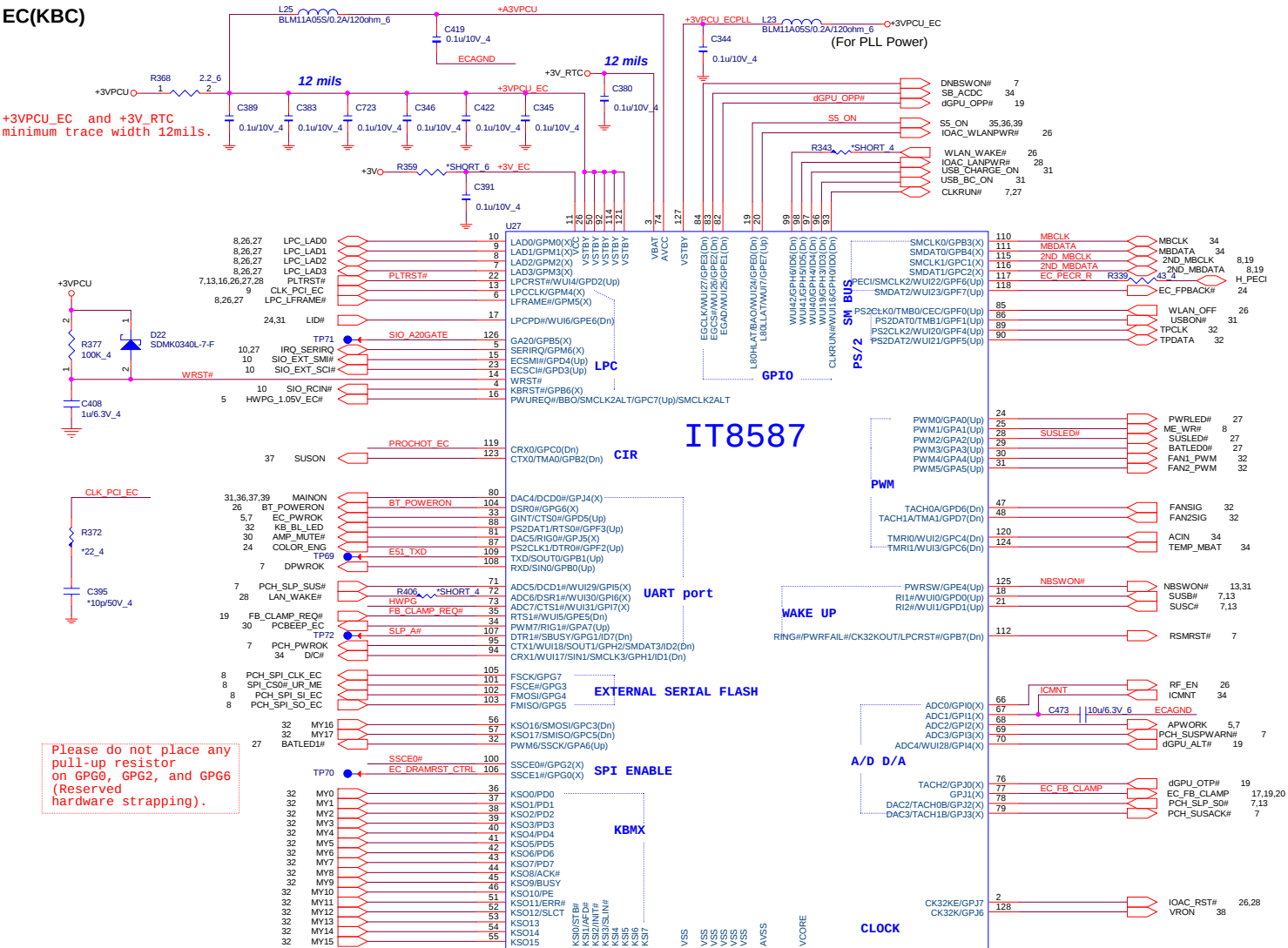
CPU FAN1 (THM)



CPU FAN2 (THM)



EC(KBC)

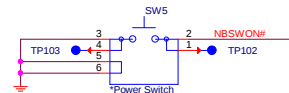


SM BUS PU(KBC)

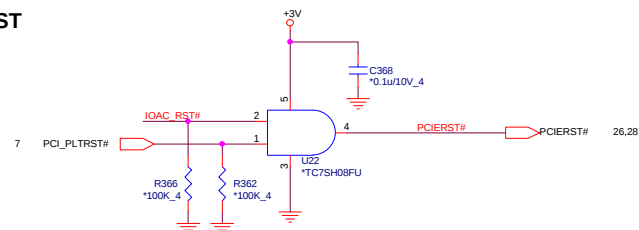
HWPB(KBC)

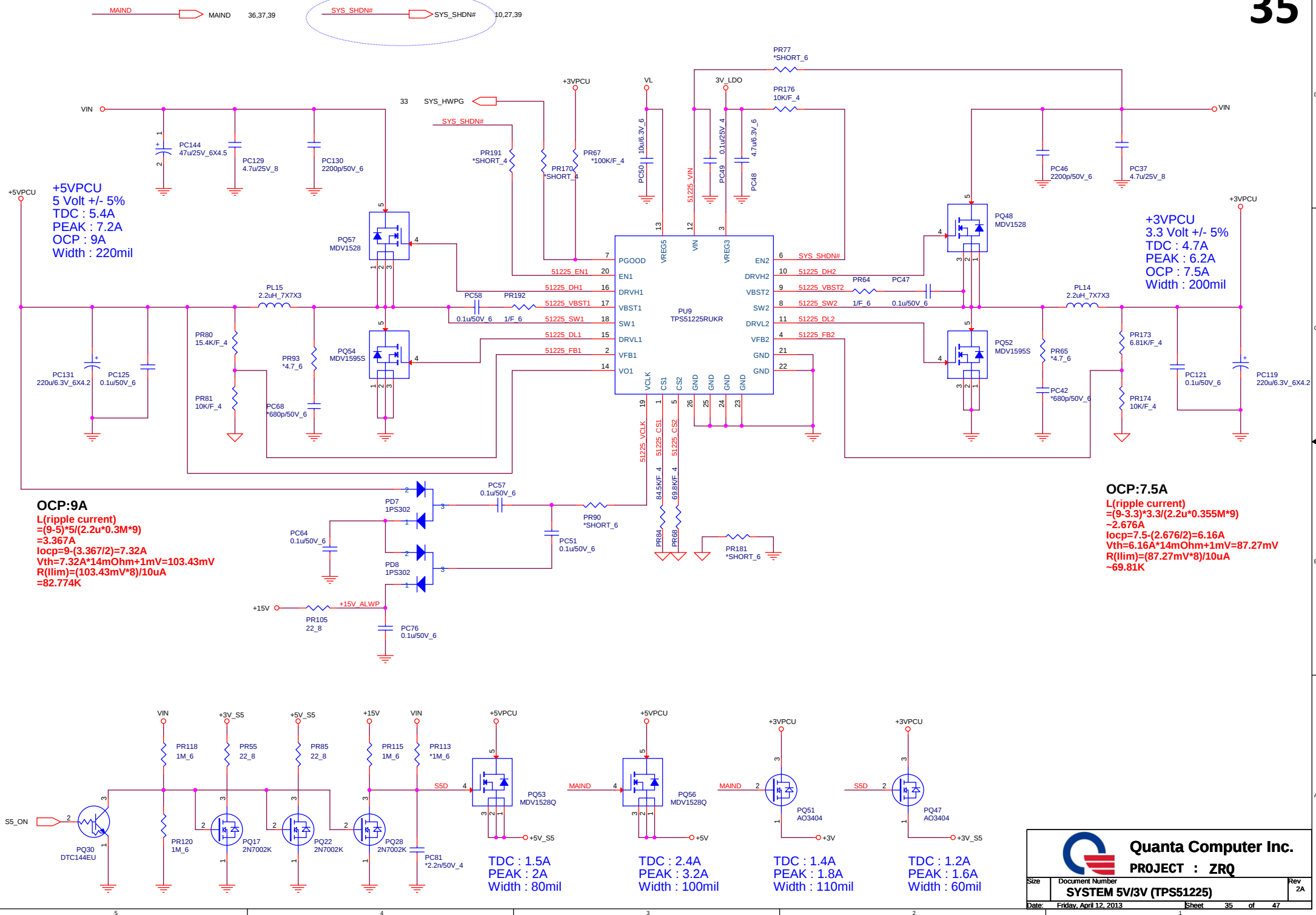
DDR=1.5V, D1 DNP and D2 POP
DDR=1.35V, D1 POP and D2 DNP

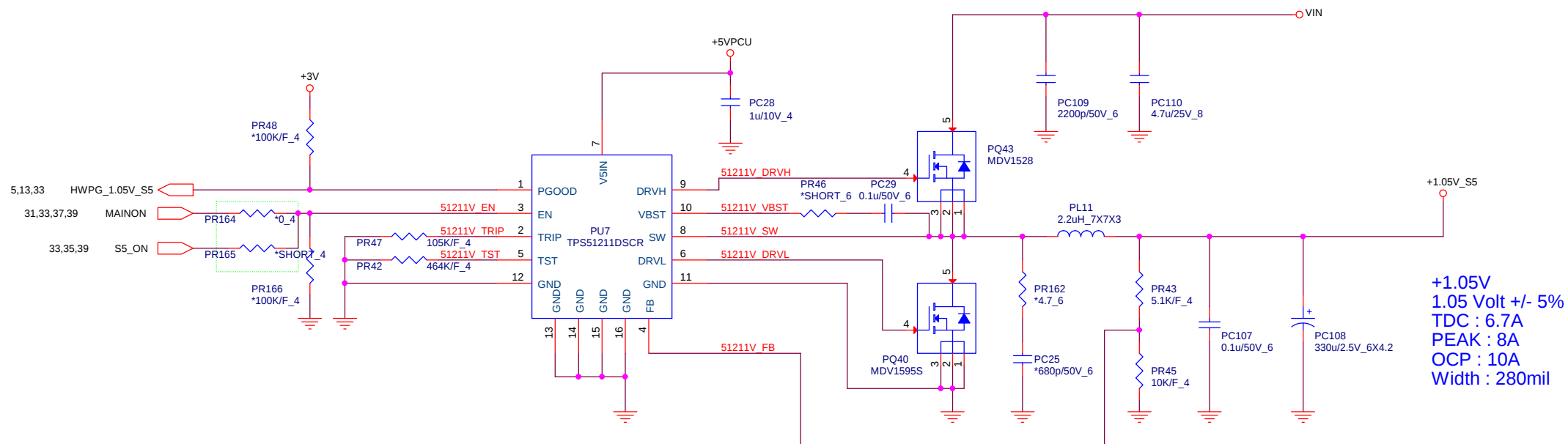
For test only



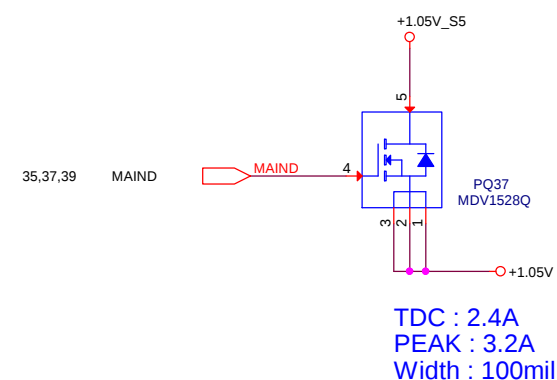
IRST







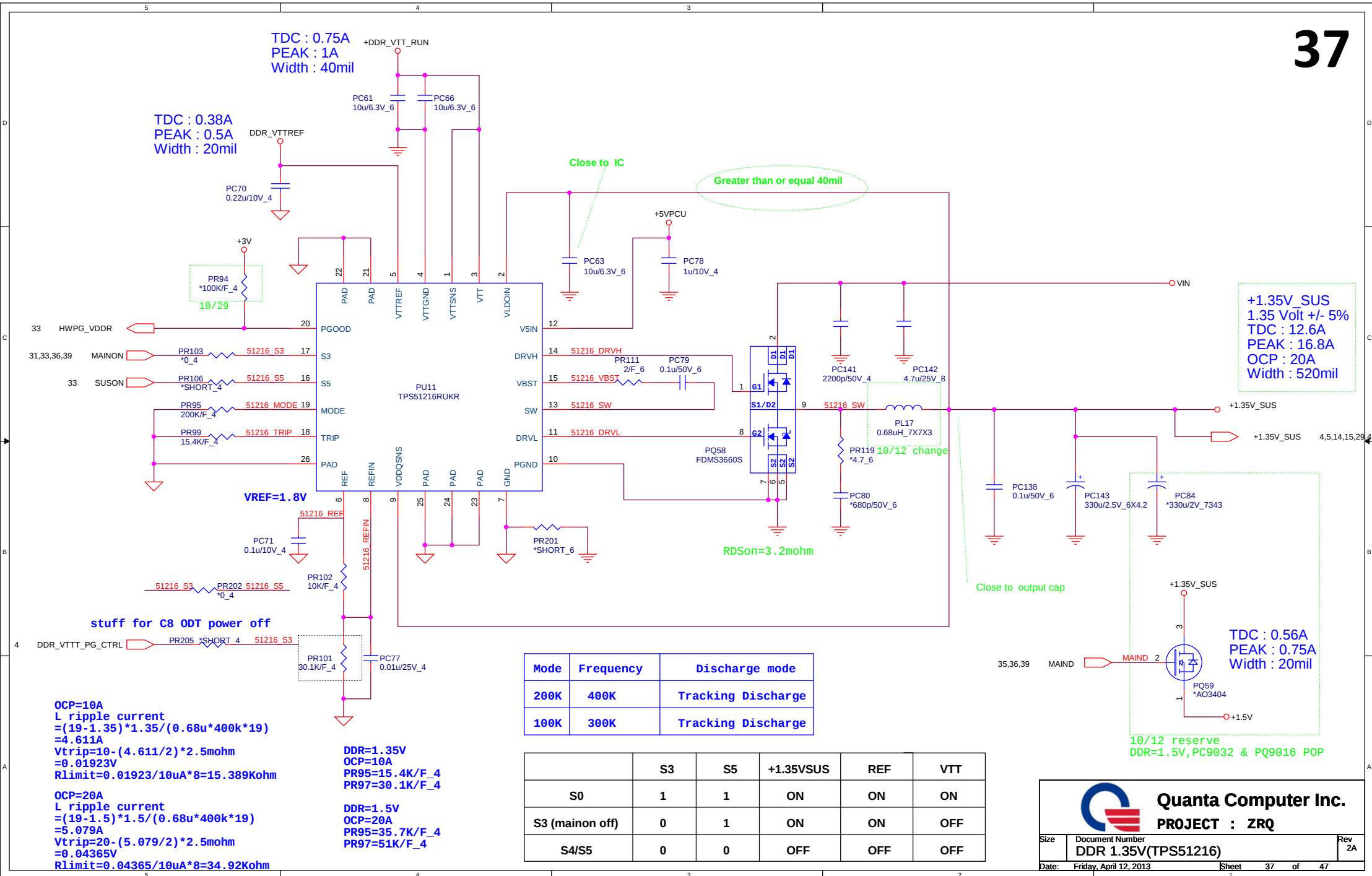
OCP=10A
 L ripple current
 $= (19 - 1.05) * 1.05 / (2.2u * 290k * 19)$
 $= 1.555A$
 $V_{trip} = 10 - (1.555 / 2) * 14mohm$
 $= 0.129V$
 $R_{limit} = 0.129 / 10uA * 8 = 103.293Kohm$



Quanta Computer Inc.
PROJECT : ZRQ

Size	Document Number	Rev
	+1.05V(TPS51211)	2A

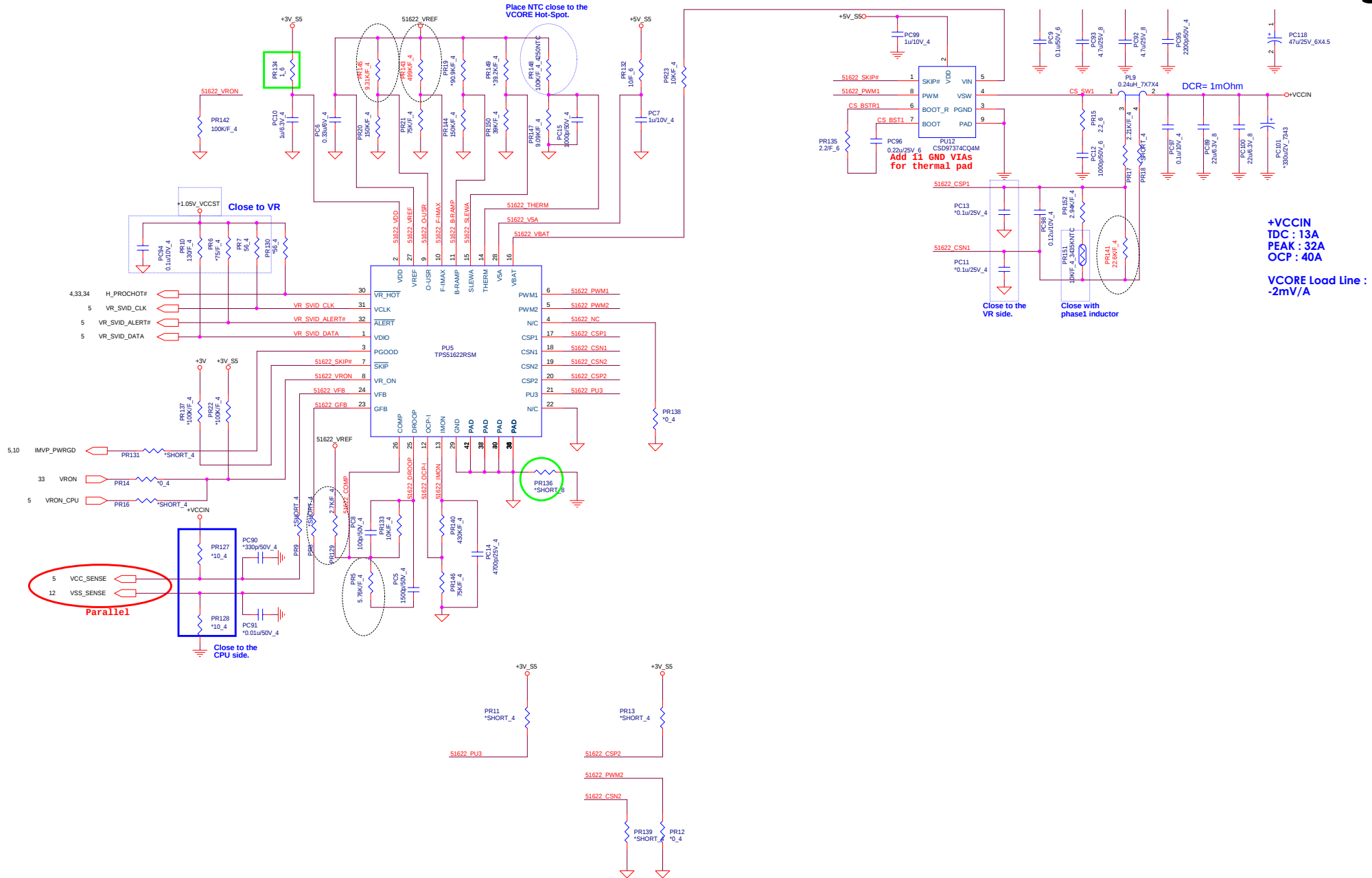
Date: Friday, April 12, 2013 Sheet 36 of 47



Quanta Computer Inc.
PROJECT : ZRQ

Size Document Number
DDR 1.35V(TPS51216) Rev 2A

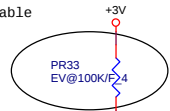
Date: Friday, April 12, 2013 Sheet 37 of 47





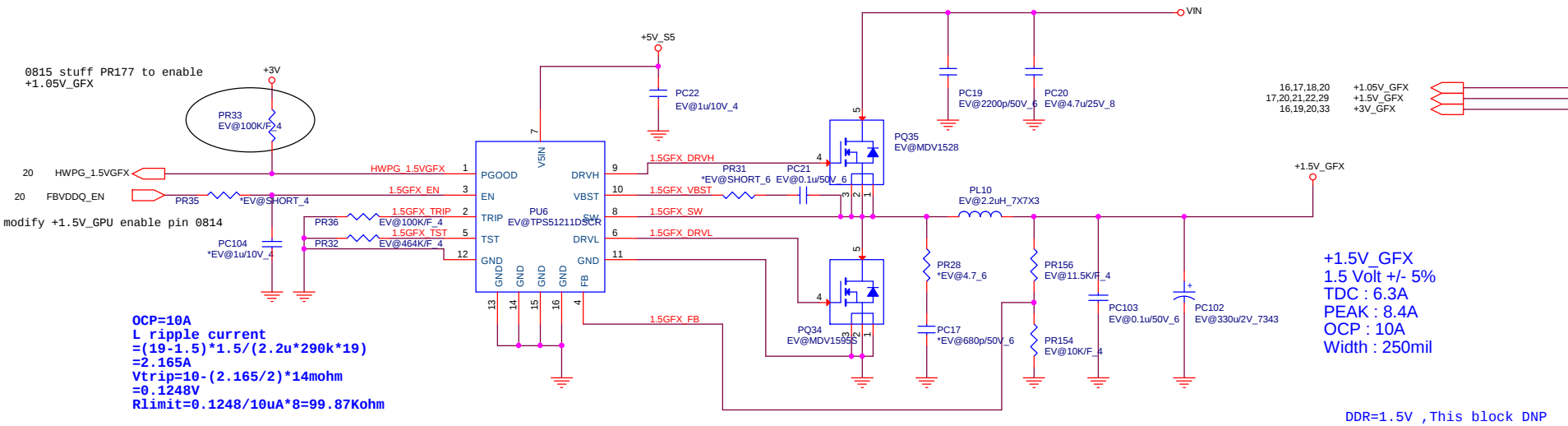


0815 stuff PR177 to enable
+1.05V_GFX



modify +1.5V_GPU enable pin 0814

OCP=10A
L ripple current
 $= (19-1.5) * 1.5 / (2 * 2u * 290k * 19)$
 $= 2.165A$
 $V_{trip} = 10 - (2.165 / 2) * 14mohm$
 $= 0.1248V$
 $R_{limit} = 0.1248 / 10uA * 8 = 99.87Kohm$



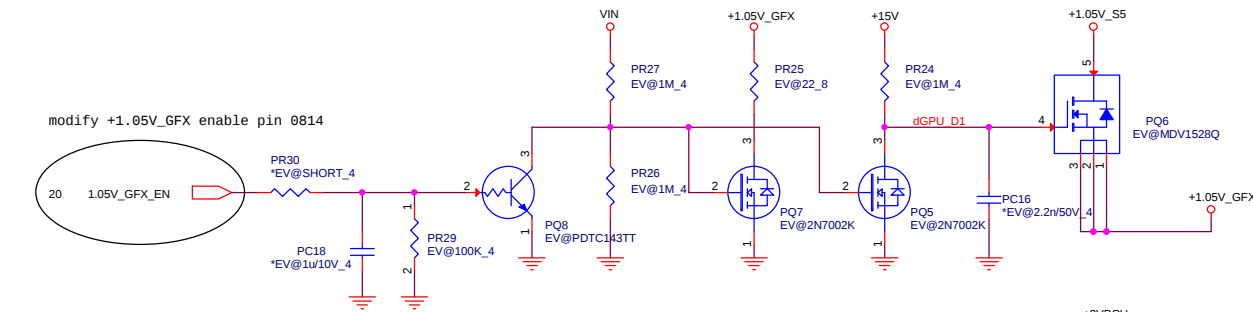
+1.5V_GFX
1.5 Volt +/- 5%
TDC : 6.3A
PEAK : 8.4A
OCP : 10A
Width : 250mil

DDR=1.5V ,This block DNP

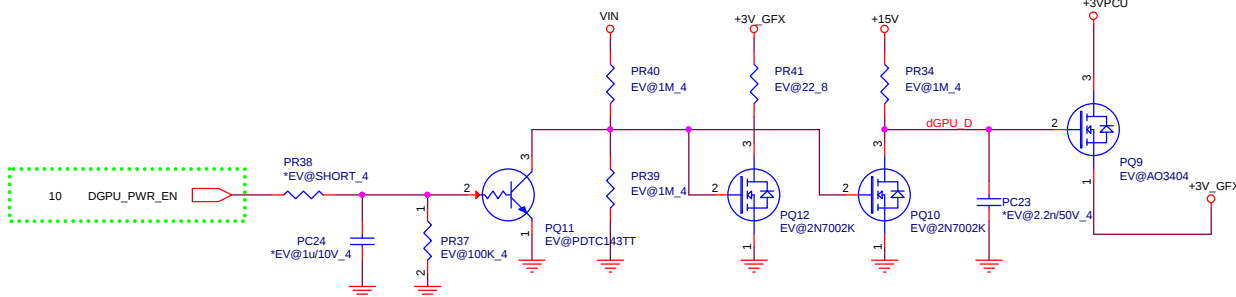
modify +1.05V_GFX enable pin 0814



+1.05V_GFX
TDC : 2.3A
PEAK : 3A
Width : 100mil

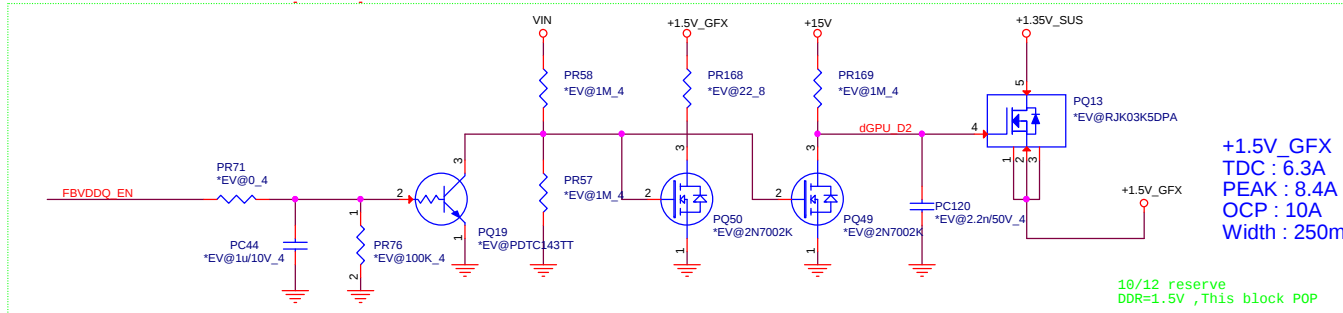


+3V_GFX
TDC : 0.76A
PEAK : 1A
Width : 40mil

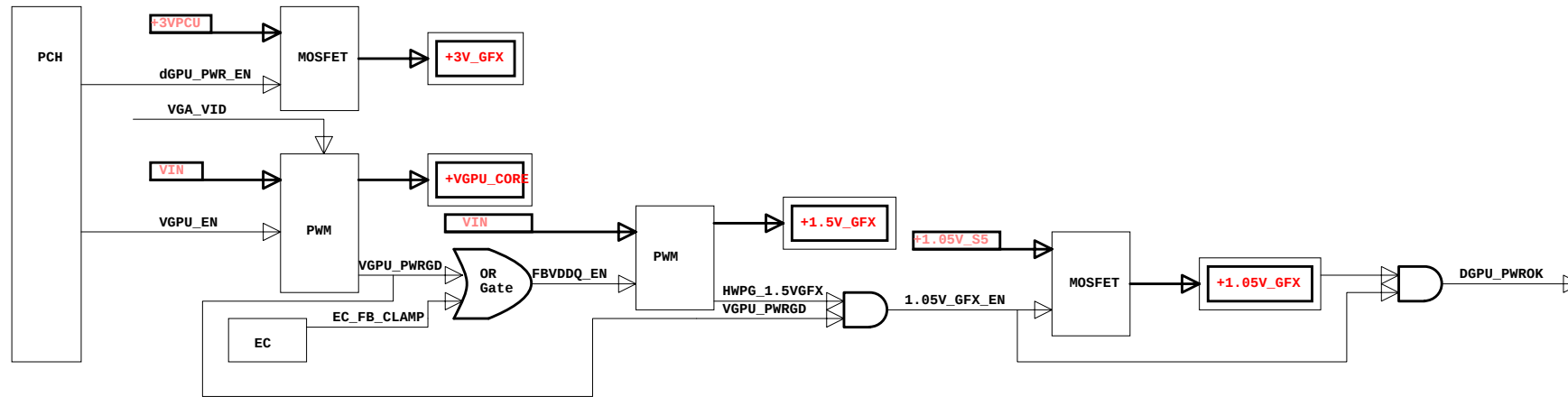


+1.5V_GFX
TDC : 6.3A
PEAK : 8.4A
OCP : 10A
Width : 250mil

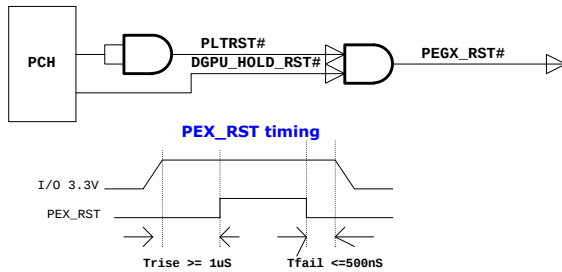
10/12 reserve
DDR=1.5V ,This block POP



VGA power up sequence



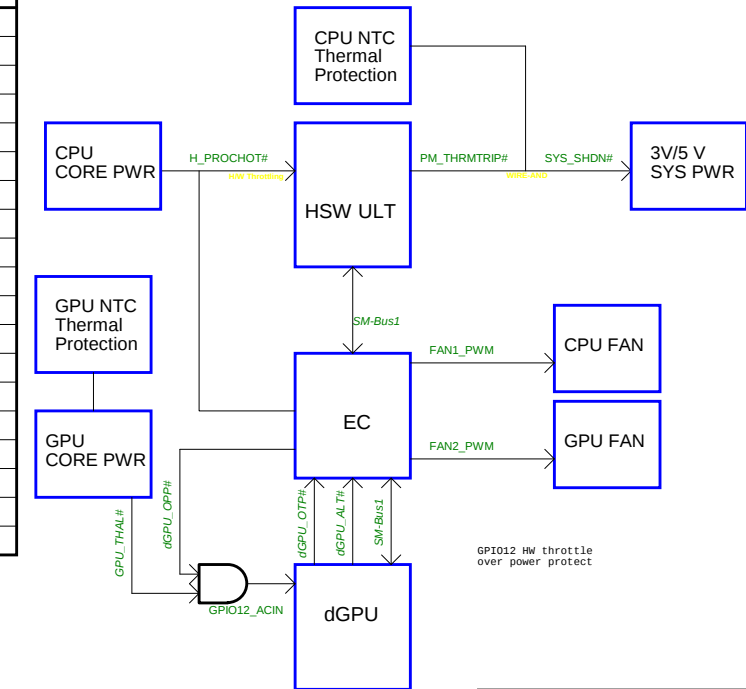
VGA Reset



Power States

POWER PLANE	VOLTAGE	DESCRIPTION	CONTROL SIGNAL	ACTIVE IN
VIN	+10V~+19V	MAIN POWER	ALWAYS	ALWAYS
+3V_RTC	+3V~+3.3V	RTC POWER	ALWAYS	ALWAYS
+3VPCU	+3.3V	EC POWER	ALWAYS	ALWAYS
+5VPCU	+5V	USB CHARGE POWER	ALWAYS	ALWAYS
+15V	+15V	CHARGE PUMP POWER	ALWAYS	ALWAYS
+3V_S5	+3.3V	LAN/BT POWER	S5_ON	S0-S5
+5V_S5	+5V	USB POWER	S5_ON	S0-S5
+5V	+5V	HDD/SPK/HDMI POWER	MAINON	S0
+3V	+3.3V	PCH/GPU/Peripheral component POWER	MAINON	S0
+1.35VSUS	+1.35V	CPU/SODIMM/MD POWER	SUSON	S0-S3
+DDR_VTT_RUN	+0.675V	SODIMM/MD Termination POWER	MAINON	S0
LCDVCC	+3.3V	LCD POWER	LVDS_VDDEN	S0
+1.5V	+1.5V	MINI CARD/NEW CARD POWER	MAINON	S0
+1.05V	+1.05V	PCH CORE VCCST POWER	MAINON	S0
+VCCIN	variation	CPU CORE POWER	VRON	S0
+VGPU_CORE	variation	External GPU POWER	VGPU_EN	S0
+3V_GFX	+3.3V	External GPU POWER	dGPU_PWR_EN	S0
+1.5V_GFX	+1.5V	External GPU POWER	FBVDDQ_EN	S0
+1.05V_GFX	+1.05V	External GPU POWER	1.05V_GFX_EN	S0

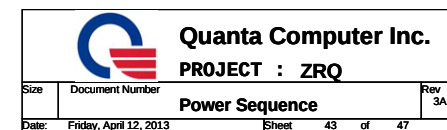
Thermal Follow Chart

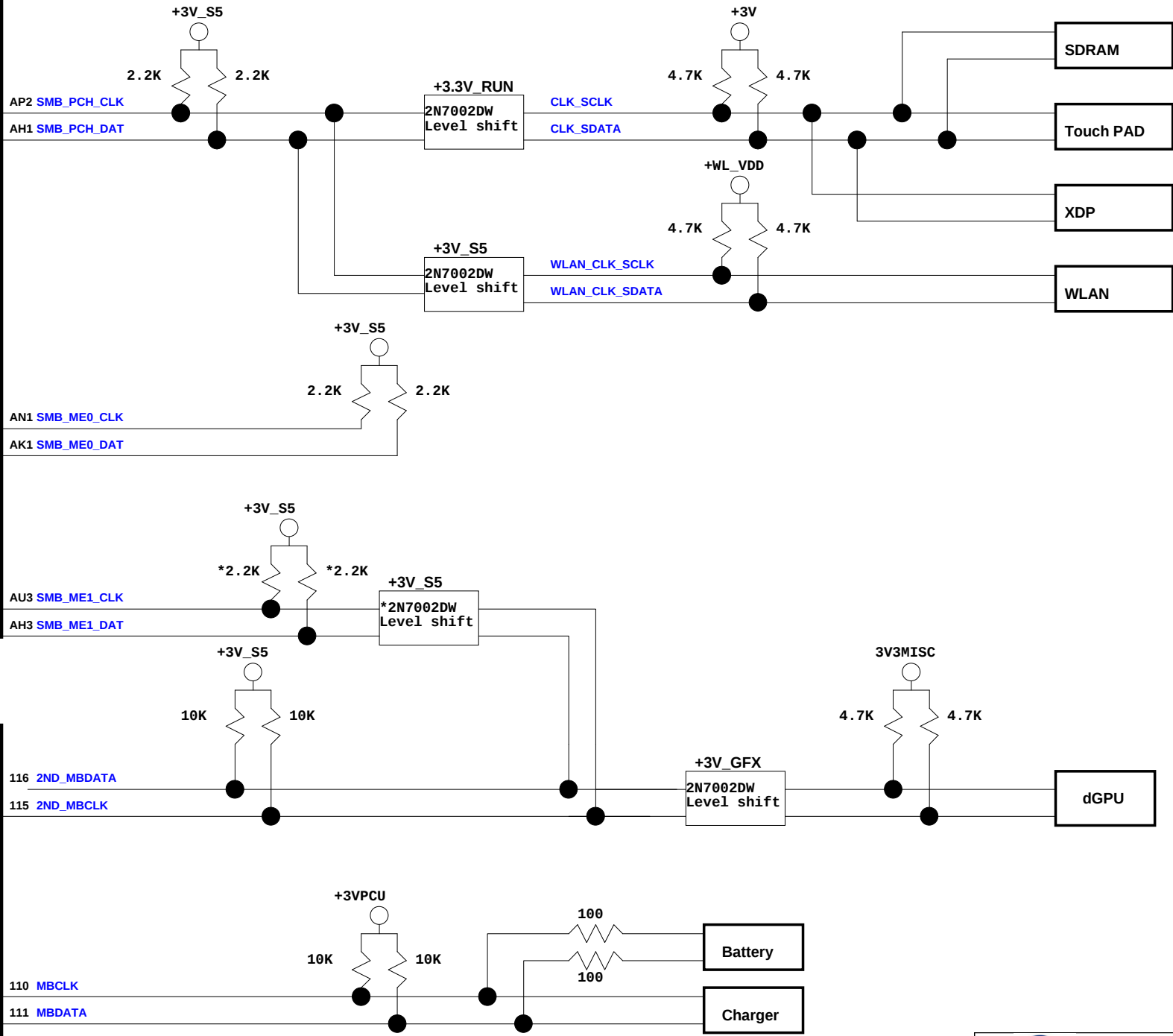
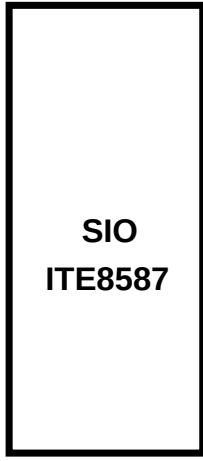
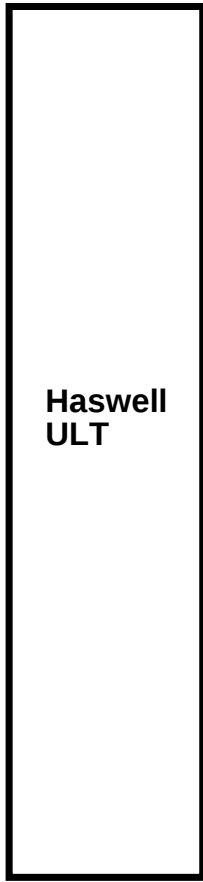


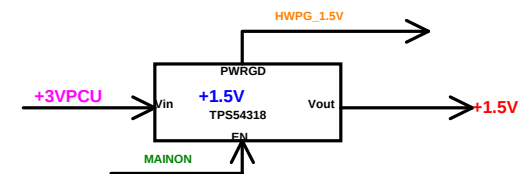
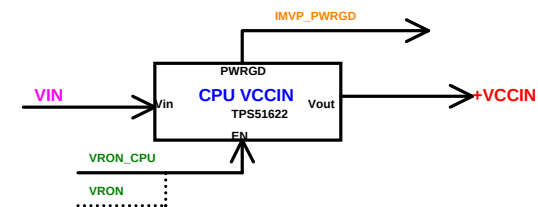
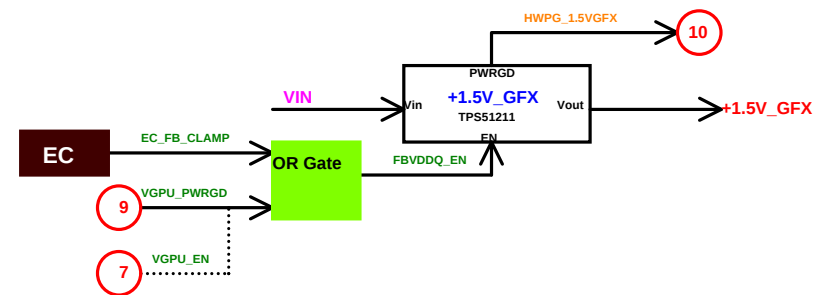
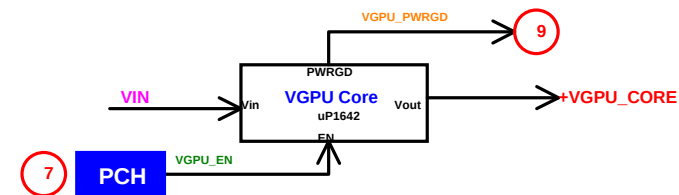
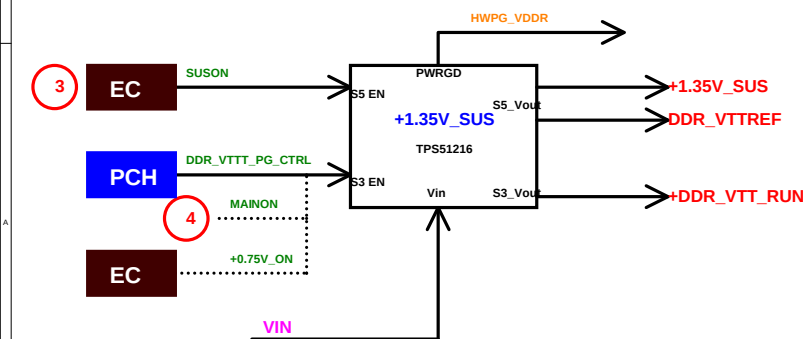
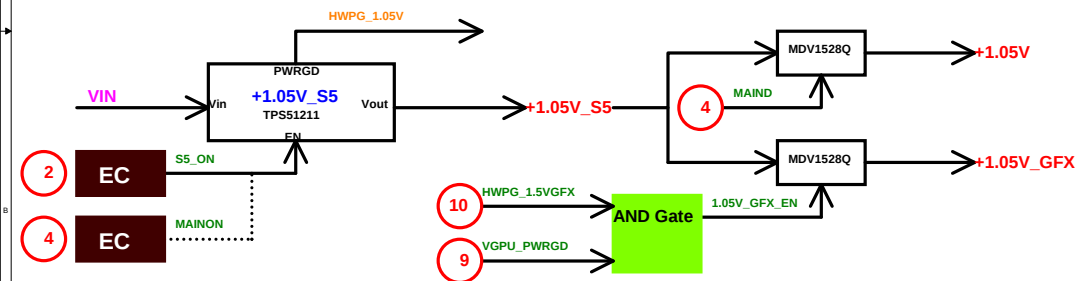
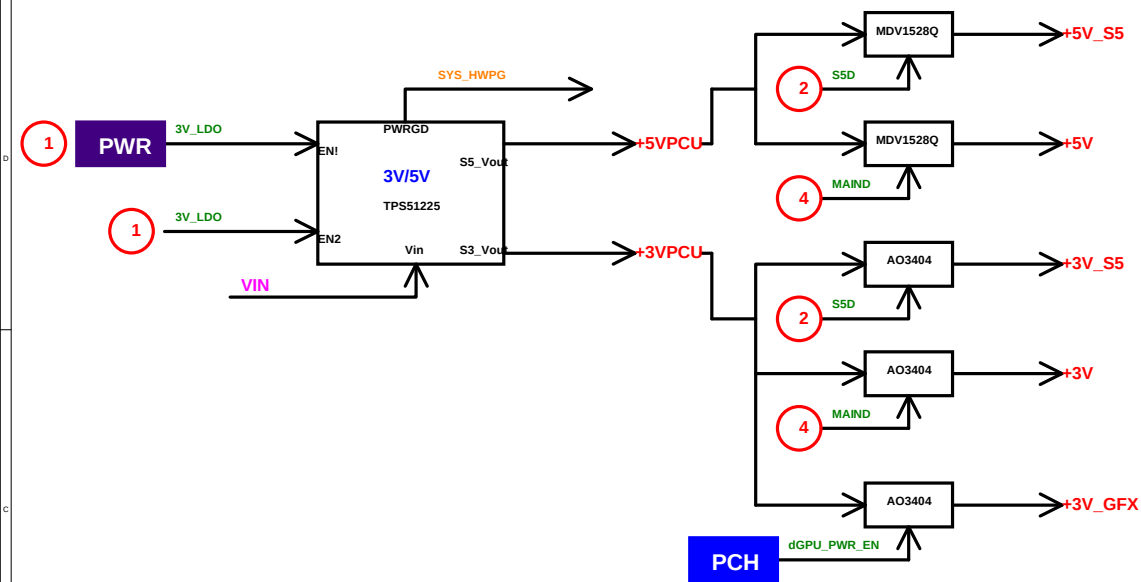
dGPU_OPP# EC notify HW throttle over power protect
dGPU_ALT# for ADPS circuit to inform EC NV dGPU VPS Alert
dGPU_OTP# VGA thrmtrip# => inform EC over temperature protect

Support Deep Sx

depend on A measure
result to implement
for B test







Model	Version	CHANGE LIST			
ZRQ	1A				
2A		1	Add R886 Pull-down for EDP_JPD(Intel check List)(Page 62)		
		2	Add RB11 and reserve RB09 for Codes Vendor request.(Page 30)		
		3	Change R345 footprint from 6402 to 6603.(Page 14)		
		4	Change U10 to correct PN AL007534001.(Page 31)		
		5	Improve IMVP_PWBGD voltage to low , to del R86_Q9 , R51_Q50 ,R495 and add U55 , C767 , RB07 .(Page 18)		
		6	Change CN12 to 12 PIN connect ,DFFC12FR034 (Page 31)		
		7	Change SW6 from DHP00BTEPV00 to DHPATE2CK03.(Page 29)		
		8	Move Hall sensor function to USB0.B.(Page 24)		
		9	Add R828 100K PD for MAINON, Upgrade U27 from AJ085470F02 to AJ085470F03 .(Page33)		
		10	Collect netname +V1_85S_VCCPCPU to +V3_3S_VCCSDIO .(Page11)		
		11	Q7 change from PMF780SN to BAW70020002 .(Page25)		
		12	Correct U41 footprint to s00p5-p-a-tchb1a-b .(Page23)		
		13	Change LE5D5.LED6 P/N from BEB00024ZA0 to BEB0002EZA0 .(Page27)		
		14	Del Q5 ,Q47,R51,R25 , add U56,C768 .(Page13)		
		15	DEL PL5,PL6,PL7,PL8 .(Page34_power)		
		16	Change PR145 from CS28872FB08 to CS29312FB13 .(Page38_Power)		
		17	Change PR143 from CS45362FB00 to CS44992FB11 .(Page38_Power)		
		18	Change PR129 from CS22672FB12 to CS22702FB14 .(Page38_power)		
		19	Change PR5 from CS1002FB26 to CS25762FB01 .(Page38_Power)		
		20	Change PR141 from CS32432FB19 to CS32262FB15 .(Page38_Power)		
		21	Change PC123 from CC64704MZ10 to CH6104KEA00 .(Page40_Power)		
		22	Add PC152,PC153,PC154 to CH6104KEA00 .(Page40_Power)		
		23	Change PL12,PL13 from CV+24P0MZ00 to CV+36T0MZ01 10X10 size .(Page40_Power)		
		24	SWAP USB0 and USB1 .(Page09)		
		25	Change CN27 to DFHS52FR044 ,same as CN18 (Page 26)		
		26	add CN12 PIN4 for USBPWR3 .(Page 31)		
		27	CN9 change footprint to dp-adis0022-p001a-20p-smt .(Page 23)		
		28	Dpop R728 and Pop R727 to save Deep S3 can't wakep issue .(Page 10)		
		29	Del C429 .(Page20)		
		30	Add R826(VRON) ,R827(SON) 100K to Gnd .(Page33)		
		31	Change CN9 PN to DFTD20FR001 .(Page23)		
		32	Add C735 ,0.1u for Vendor request .(Page28)		
		33	Add C736 ,0.1u and reserve C727 ,47u for Vendor request .(Page28)		
		34	Change R348 Pu sign to +3V .(Page28)		
		35	TEMP_MBAT from battery connect pin 5 to pin 6 (BATT_EN0) .(Page34)		
		36	Change R354(PCH_PWROK) from 10 k to 100K .(Page07)		
		37	Reverse RB00 ,RB10 ,0 Ohm .(Page30)		
		38	Change JP18 Packing and PN same as JP19 .(Page37)		
		39	Add RB35 for Vendor request .(Page23)		
		40	Change R491 from 1M to 5.1M .(Page23)		
		41	Change R491 from 121 to 120ohm(Intel Check list) .(Page04)		
		42	Change SUSL_EDP power from +3V_S5 to +3V_PCV .(Page27)		
		43	Change CN13 to DFHS00F5047 10-p_du0 to PE request. Footprint is "gs12401-1011-40p-e-sub-smt.(Page24)		
		44	VCP1_PSN Pull high from +3V to +3V_S5 .(Page40)		
		45	B-SMT USE RTL841BA-CC need Dpop R295 and change U21 PN to AL008411004 .(Page28)		
		46	C596,C591 change from 18P to 12PV6 .(Page09)		
		47	C278,C284 change from 27P to 12PV6 .(Page08)		
		48	Dpop R147,R106,R04,R534 and Pop R01,R05,R146,R533 to support Qual Mode.(Page10)		
		49	Pop P01044.(Page40_Power)内部行文		
		50	Change PU8 from AL001642000 to AL001642001 .(Page40_Power)内部行文		
		51	PC6 EOD Part change to CH4331K9006 .(Page38_Power)		
		52	PC3,PC35 EOD Part change to CH21506KB14 .(Page38_39_Power)		
		53	Change U27 from AJ083870F03 to AJ083870F04 .(Page33)内部行文		
		54	Add level shift function.(Page25)		
		55	Dpop PR75 .(Page40_Power)内部行文		
		56	Change PC15 to 1000p_50V(CHE1006J010) .(Page38_Power)内部行文		
		57	Dpop PR75 .(Page40_Power)内部行文		
3A		1	Dpop R226 ,Pop Q26(BAW70020002) ,R795 (CS31002FB20) for CG6 function.(Page19)		
		2	Swap Pin 25 and Pin 32.(Page33)		
		3	Del D31,C319 , and Add Q69,C738,CR22,CR23,CR24 for SDA request.(Page23)		
		4	Add Test Pad on SW5_SWB for SMT request.(Page27,33)		
		5	Add C317 ,47u for Vendor request.(Page28)		
		6	SWAP CLKOUT_PCIE .(Page09)		
		7	Pop R477 ,R478 ,R479 ,R480 _000hm(CS11002FB22)for HDMI EMI Issue.(Page25)		
		8	Pop C655,C654 _10p(CB1006J000) for SD CLK EMI Issue .(Page29)		
		9	Pop B1ch,C399 _22p(CB2206J000) for EMI Issue .(Page30)		
		10	DelPop PR117 .(Page34)		
		11	C285 change from 0402 to 0603 size .(Page28)		
		12	Del CNS,C272,C253 footprint .(Page13)		
		13	Dpop R336 ,Pop R533 for Lan can't link to exlurer .(Page28)		
		14	Dpop R348 .(Page28)		
		15	Reserve RB12 for PCH_LAN_WAKE# .(Page26)		
		16	Add RB15,C740 and pop R310 for software of Lan VCC.(Page20)		
		17	R608 connect to CLK_PCIE_REQ49 .(Page09)		
		18	Dpop SW7 .(Page23)		
		19	Del JP Position 8,001F ,3729 (CS+0010F100) ,JP5 ,JP6 ,JP10 ,JP11 ,JP12 ,JP13 ,JP14 ,JP15 ,JP17 ,JP18 ,JP19 ,JP20 ,JP21 ,JP16 .		
		20	Del 0_4 (CS00002J030) to SHORT PAD_4 : PR0,PR0,PR11,PR13,PR16,PR18,PR30,PR31,PR36,PR44,PR61,PR66,PR63,PR106,PR131,PR139,PR165,PR170,PR178,PR180,PR185,PR191,PR193,PR194,PR196,PR200,PR204,PR205,PR209,PR211,PR217,PR106		
		21	Del 0_6 (CS00003J951) to SHORT PAD_6 : PR31,PR46,PR54,PR77,PR90,PR181,PR201,PR203,PR215,PR158		
		22	Del 0_8 (CS00004J400) to SHORT PAD_8 : PR136		
		23	Add RB13 ,0 OHM.(Page26)		
		24	Change C740 from 0603 to 0402 size.(Page28)		
		25	Dpop Q39 , R276 ,Pop R321 and change R320 to 1K to meet Lmwake signal spec.(Page28)		
		26	Pop R54,R47,R49,R55,R49,R48,R48,R48内部行文		
		27	Del JP7 ,JP8 ,JP9(CS+001AGM13).(Page05)		
		28	Change to 0402 shortpad:R45,R69,R177,R215,R236,R237,R239,R274,R277,R283,R288,R311,R320,R334,R353,R440,R409,R419,R423,R424,R425,R426,R430,R432,R434,R448,R449,R450,R513,R570,R573,R587,R591,R596,R625,R641,R652,R653,R678,R695,R712,R719,R722,R733,R734,R735,R736,R741,R758,R759,R760,R761,R762,R763,R764,R765,		
		29	Change to 0603 shortpad:R107,R111,R150,R194,R197,R212,R229,R233,R234,R252,R269,R290,R303,R304,R330,R350,R351,R352,R356,R358,R441,1415,R418,R422,R431,R433,R440,R441,R442,R443,R444,R445,R446,R447,R540,R745,R746,R767		
		30	Change to 0805 shortpad:R165,R174,R179,R190,R217,R268,R270,R452,R470,R559,R560,R732,R737,R749		
		31	Change R400,R420 from 47 ohm to 50 ohm.(Page30)		
		32	Change R411,R422 from shortpad to 0603 Footprint.(Page30)		

Model	Version	CHANGE LIST				
ZRQ	3B	1 R276 change fro to 10K to 1K , Dpop R328. (PCIE_LAN_WAKE#), 内部行文 2 Change C24 KB Conn P8 to DFF C26FR063. (Page 32), 内部行文 3 Change U27 E.C to E version AH05670F05. (Page 33), 内部行文 4 Fine tune Amp Gain =>R422,R411 change from 0 ohm to 1k , and pop R421,R410 to 1.62K. (Page 30) 5 Change TEMP_MBAT from Pin 6 to Pin 5 of P.J1. (Page 34) 6 Dpop Q24 , and Add R228 to solve level abnormal issue for CG6. (Page 19) 7 Add RE16 and net "LB_PWR_CNN_Q" to stuff Q69 always for safety issue. (Page 19) 8 Reserve R855,R859 and add R854,R857. (Page 23) 9 For WIKI Change USB Port1 and Port4 10 Add new on Board RAM HYNIX H5TC4G63AFR-PRBA RAM 1D:0000 11 Del L35,L36,L6,L7,L8,L29,L12,L13,L32,L16,L34				
	3C	1 Change to 0402 shortpad: R725,R724,R711,R716,R26,R27,R28,R29,R32,R33,R483,R484,R493,R492,R56,R57,R58,R59, R96,R89,R669,R664,R702,R838,R639,R651,R225,R346,R355,R770,R705,R790,R73 , R455,R456,R457,R458,R459,R343,R406,R596 2 For HDMI 7-2 issue change R37,R38,R39,R40,R41,R42,R43,R44 To 470 ohm and remove R478,R479,R477,R480 (Page 25) 3 For T1 HD3S2521 issue R77,R79,R592,R503 need mount 10K, change R528 from 100 ohm to 0 ohm and remove R854,R857 , add R855,R859. (Page 23) 4 Change to 0603 shortpad: R373,R337,R382,R297,R235,R326,R322,L30,R385,R220,R254,R359				
	3F	1. Add C245 for intel request for G3 can't boot issue				
DOC NO.	PROJECT MODEL	ZRQ	APPROVED BY:		DATE:	
	PART NUMBER:		DRAWING BY:		REVISION:	
			Quanta Computer Inc. PROJECT : ZRQ Change list-2			